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Nyquest Technology Co., Ltd.

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NY8TM52D

6 I/O 8-bit MTP-Based MCU with 4-key Touch Pad

Version 1.1

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1. 概述

NY8TM52D是以MTP作為程式記憶體 8 位元微控制器，適合IO產品的應用，例如遙控器、風扇/燈光控制或是遊樂器周邊等等。而MTP作為程式記憶體更方便且有效率的開發產品。NY8TM52D核心建立在RISC精簡指令集架構可以很容易地做編輯和控制，共有 55 條指令。除了少數指令需要 2 個時序，大多數指令都是 1 個時序即能完成，可以讓使用者輕鬆地以程式控制完成不同的應用。因此非常適合各種中低記憶容量但又複雜的應用。

在I/O的資源方面，NY8TM52D有 6 根彈性的雙向I/O腳，每個I/O腳都有單獨的暫存器控制為輸入或輸出腳。而且每一個I/O腳位都有附加的程式控制功能如上拉或下拉電阻或開漏極(Open-Drain) 輸出。此外針對紅外線搖控的產品方面，NY8TM52D內建了可選擇頻率的紅外載波發射口。其中有 4 根I/O具備觸控開關功能，可經由暫存器控制為觸控開關輸入腳位。NY8TM52D內建電壓比較器，亦可藉由暫存器選擇I/O當電壓輸入與比較結果輸出。

NY8TM52D有兩組計時器，可用系統頻率當作一般的計時的應用或者從外部訊號觸發來計數。另外NY8TM52D提供 3 組 10 位元解析度的PWM輸出及一組蜂鳴器輸出，可用來驅動馬達、LED、或蜂鳴器等等。

NY8TM52D採用雙時鐘機制，高速振盪或者低速振盪都由內部RC振盪輸入。在雙時鐘機制下，NY8TM52D可選擇多種工作模式如正常模式(Normal)、慢速模式(Slow mode)、待機模式(Standby mode) 與睡眠模式(Halt mode)可節省電力消耗延長電池壽命。

在省電的模式下如待機模式(Standby mode)與睡眠模式(Halt mode)中，有多種事件可以觸發中斷喚醒NY8TM52D進入正常操作模式(Normal) 或 慢速模式(Slow mode) 來處理突發事件。

1.1 功能

- 寬廣的工作電壓：
 - 2.4V ~ 5.5V @系統頻率 \leq 8MHz。
 - 3.0V ~ 5.5V @系統頻率 $>$ 8MHz。
- 寬廣的工作溫度：-40°C ~ 85°C。
- 2Kx14 bits MTP。
- 128 bytes SRAM。
- 6 根可分別單獨控制輸入輸出方向的I/O腳(GPIO)、PB[5:0]。
- PB[3:0]可選擇輸入時使用內建下拉電阻。
- PB[5:0]可選擇上拉電阻或開漏極輸出(Open-Drain)。
- 8 層程式堆棧(Stack)。
- 存取資料有直接或間接定址模式。
- 一組 8 位元上數計時器(Timer0)包含可程式化的頻率預除線路。
- 一組 10 位元下數計時器(Timer1)可選重複載入或連續下數計時。
- 三個 10 位元的脈衝寬度調變輸出(PWM1/2/3)。
- 一個蜂鳴器輸出(BZ1)。
- 38/57KHz紅外線載波頻率可供選擇，同時載波之極性也可以根據數據作選擇。

- 內建上電復位電路(POR)。
- 內建低壓復位功能(LVR)。
- 內建 16.段低電壓偵測功能(LVD)。
- 內建準確的電壓比較器(Voltage Comparator)。
- 內建 4 鍵觸控輸入腳
- 內建看門狗計時(WDT)，可由程式韌體控制開關。
- 雙時鐘機制，系統可以隨時切換高速振盪或者低速振盪。
 - 高速振盪: I_HRC (1~20MHz內部高速RC振盪)
 - 低速振盪: I_LRC (內部 32KHz低速RC振盪)
- 四種工作模式可隨系統需求調整電流消耗：正常模式(Normal)、慢速模式(Slow mode)、待機模式(Standby mode) 與 睡眠模式(Halt mode)。
- 八種硬體中斷：
 - Timer0 溢位中斷。
 - Timer1 借位中斷。
 - WDT 中斷。
 - PB 輸入狀態改變中斷。
 - 外部中斷輸入。
 - 低電壓偵測中斷。
 - 觸控比較器中斷。
 - 觸控計數器溢位中斷。
- NY8TM52D在待機模式(Standby mode)下的八種喚醒中斷：
 - Timer0 溢位中斷。
 - Timer1 借位中斷。
 - WDT 中斷。
 - PB 輸入狀態改變中斷。
 - 外部中斷輸入。
 - 低電壓偵測中斷。
 - 觸控比較器中斷。
 - 觸控計數器溢位中斷。
- NY8TM52D在睡眠模式(Halt mode)下的五種喚醒中斷：
 - WDT 中斷。
 - PB 輸入狀態改變中斷。
 - 外部中斷輸入。
 - 觸控比較器中斷。
 - 觸控計數器溢位中斷。
- NY8TM52D提供兩種電流檔位(Normal/Large)

1. General Description

NY8TM52D is a MTP based 8-bit MCU tailored for I/O based applications like remote controllers, fan/light controller, game controllers, toy and various controllers. The MTP offers the advantage of convenient and effective way of developing user program. NY8TM52D adopts advanced CMOS technology to provide customers remarkable solution with low cost and high performance benefits. RISC architecture is applied to NY8TM52D and it provides 55 instructions. All instructions are executed in single instruction cycle except program branch and skip instructions which will take two instruction cycles. Therefore, NY8TM52D is very suitable for those applications that are sophisticated but compact program size is required.

NY8TM52D provide on-chip debug (OCD) facilities as a low cost alternative to ICE. With OCD and a minimum of extra hardware, NY8TM52D can do ICE tasks such as free running, single stepping, break point setting and internal ram/register accessing.

As NY8TM52D address I/O type applications, it can provide 6 I/O pins for applications which require abundant input and output functionality. Moreover, each I/O pin may have additional features, like Pull-High/Pull-Low resistor and open-drain output type through programming. Moreover, NY8TM52D has built-in infrared (IR) carrier generator with selectable IR carrier frequency and polarity for applications which demand remote control feature. Multiple Touch-Keys is from 1 touch key up to 4 touch keys configured by register option. A built-in LDO regulator for touch sensor can provide a stable capacitive sensing design for touch application. An innovative software tool “Q-Touch” is provided to develop the different touch applications

NY8TM52D also provides 2 sets of timers which can be used as regular timer based on system oscillation or event counter with external trigger clock. Moreover, NY8TM52D provides 3 set of 10-bit resolution Pulse Width Modulation (PWM1/2/3) output and 1 set buzzer output in order to drive motor/LED and buzzer.

NY8TM52D employs dual-clock oscillation mechanism, both high oscillation or low oscillation can be derived from internal resistor/capacitor oscillator. Moreover, based on dual-clock mechanism, NY8TM52D provides kinds of operation mode like Normal mode, Slow mode, Standby mode and Halt mode in order to save power consumption and lengthen battery operation life.

While NY8TM52D operates in Standby mode and Halt mode, kinds of event will issue interrupt requests and can wake-up NY8TM52D to enter Normal mode and Slow mode in order to process urgent events.

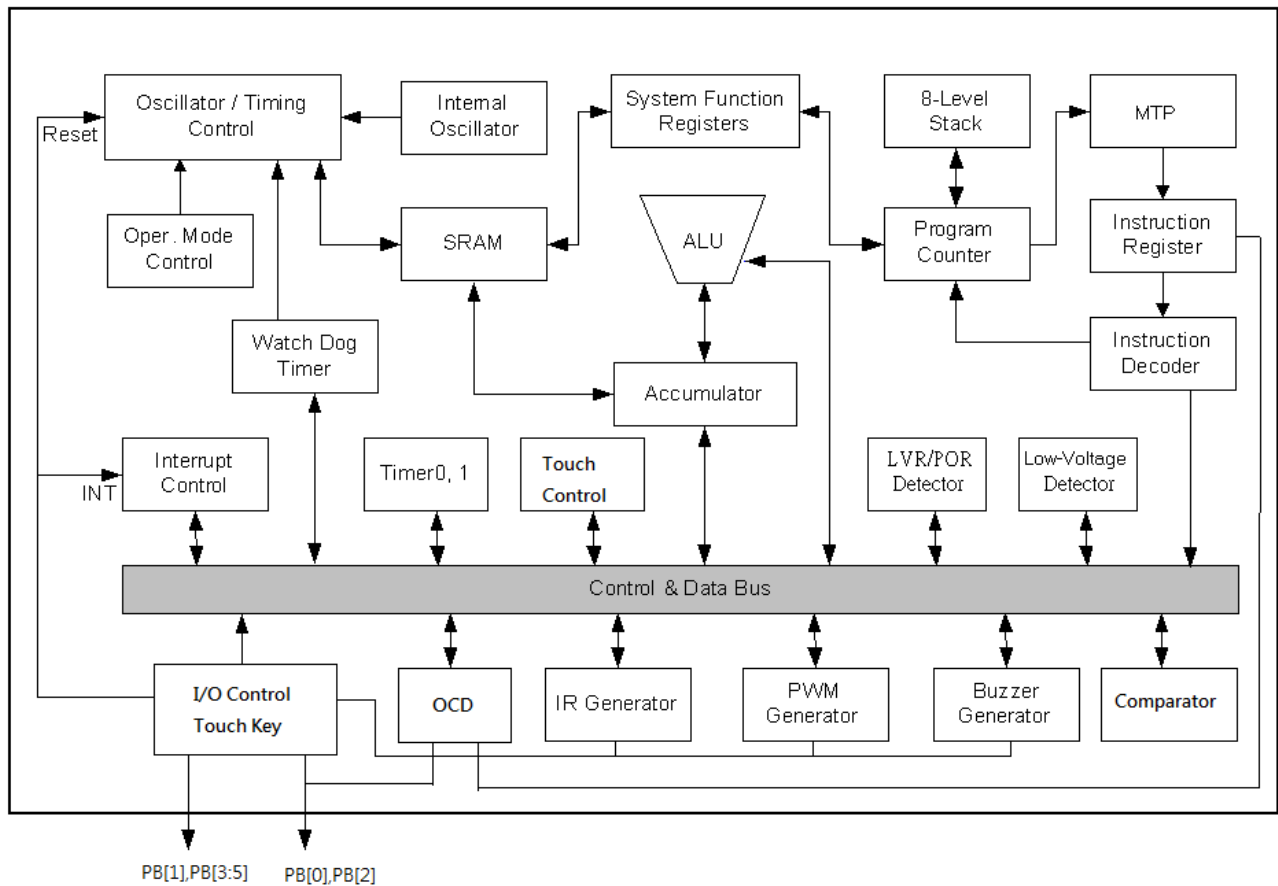
1.1 Features

- Wide operating voltage range:
 - 2.4V ~ 5.5V @system clock \leq 8MHz.
 - 3.0V ~ 5.5V @system clock $>$ 8MHz.
- Wide operating temperature: -40°C ~ 85°C.
 - 2K x 14 bits MTP.
 - 128 bytes SRAM.

- 6 general purpose I/O pins (GPIO), PB[5:0], with independent direction control.
- PB[3:0] have features of Pull-Low resistor for input pin.
- PB[5:0] have features of Pull-High resistor, and open-drain output.
- 8-level hardware Stack.
- Direct and indirect addressing modes for data access.
- One 8-bit up-count timer (Timer0) with programmable prescaler.
- One 10-bit reload or continuous down-count timers (Timer1).
- Three 10-bit resolution PWM (PWM1/2/3) output.
- One buzzer (BZ1) output.
- Selectable 38/57KHz IR carrier frequency and high/low polarity according to data value.
- Built-in Power-On Reset (POR).
- Built-in high-precision Low-voltage detector(LVD) .
- Built-in high-precision Voltage Comparator.
- Built-in 4-key Touch pad
- Built-in Low-Voltage Reset (LVR).
- Built-in 16-segment Low-Voltage Detect (LVD).
- Built-in Watch-Dog Timer (WDT) enabled/disabled by firmware control.
- Dual-clock oscillation: System clock can switch between high oscillation and low oscillation.
 - High oscillation: I_HRC (Internal High Resistor/Capacitor Oscillator ranging from 1M~20MHz)
 - Low oscillation: I_LRC (Internal 32KHz oscillator)
- Four kinds of operation mode to reduce system power consumption:
 - Normal mode, Slow mode, Standby mode and Halt mode.
- Eight hardware interrupt events:
 - Timer0 overflow interrupt.
 - Timer1 underflow interrupt.
 - WDT timeout interrupt.
 - PB input change interrupt.
 - External interrupt.
 - LVD interrupt.
 - Touch comparator interrupt
 - Touch counter overflow interrupt
- Eight interrupt events to wake-up NY8TM52D from Standby mode:
 - Timer0 overflow interrupt.
 - Timer1 underflow interrupt.

- WDT timeout interrupt.
 - PB input change interrupt.
 - External interrupt.
 - LVD interrupt.
 - Touch comparator interrupt
 - Touch counter overflow interrupt
- Five interrupt events to wake-up NY8TM52D from Halt mode:
 - WDT timeout interrupt.
 - PB input change interrupt.
 - External interrupt.
 - Touch comparator interrupt
 - Touch counter overflow interrupt
 - There are two current options (Normal/Large) can be selected.

1.2 Block Diagram



1.3 Pin Assignment

NY8TM52D provides three kinds of package type which are SOP8, DIP8 and SOT23-6.

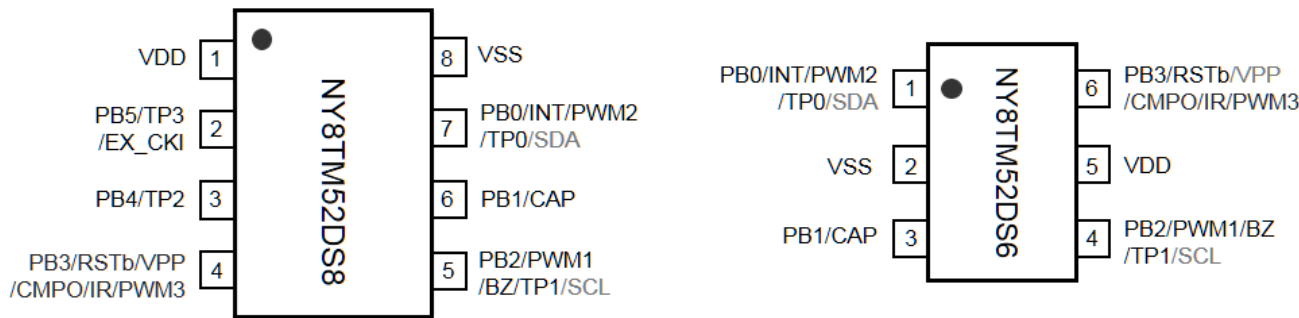


Figure 1 Package pin assignment

1.4 Pin Description

Pin Name	I/O	Description
PB0 / INT / PWM2 / TP0 / SDA	I/O	PB0 is a bidirectional I/O pin, and can be comparator analog input pin, Touch Pad.. PB0 is input pin of external interrupt when EIS=1 & INTIE=1. PB0 can be PWM2 output TP0 is Touch Pad 0 PB0 can be programming pad SDA.
PB1 / CAP	I/O	PB1 is a bidirectional I/O pin, cab be Touch PAD External Capacitor Pad. CAP is Touch PAD External Capacitor Pad
PB2 / PWM1 / BZ1 / TP1 / SCL	I/O	PB2 is a bidirectional I/O pin and can be comparator analog input pin, Touch Pad. PB2 can also be PWM1 output. PB2 can also be BUZZER1 output. TP1 is Touch Pad 1 PB2 can be programming pad SCL.
PB3 / RSTb / CMPO / VPP / IR / PWM3	I/O	PB3 is a bidirectional I/O pin. PB3 can be reset pin RSTb. If RSTb pin is low, it will reset NY8TM52D. PB3 can be the output of comparator. NY8TM52D will enter MTP programming mode if this pin is more than 9.8V. If IR mode is enabled, this pin is IR carrier output. PB3 can be PWM3 output.
PB4 / TP2	I/O	PB4 is a bidirectional I/O pin and can be comparator analog input pin, Touch Pad. PB4 also can be output of instruction clock. TP2 is Touch Pad 2
PB5 / TP3 / EX_CK1	I/O	PB5 is a bidirectional I/O pin and can be comparator analog input pin, Touch Pad. TP3 is Touch Pad 3 PB5 can also be timer clock source EX_CK1.
VDD	-	Positive power supply.
VSS	-	Ground.

2. Memory Organization

NY8TM52D memory is divided into two categories: one is program memory and the other is data memory. Data memory is sub-divided into SRAM/Register Memory.

2.1 Program Memory

The program memory space of NY8TM52D is 2K words. Therefore, the Program Counter (PC) is 11-bit wide in order to address any location of program memory.

Some locations of program memory are reserved as interrupt entrance. Power-On Reset vector is located at 0x000. Software interrupt vector is located at 0x001. Internal and external hardware interrupt vector is located at 0x008.

NY8TM52D provides instruction GOTOA, CALLA to address 256 location of program space. NY8TM52D also provides instructions LCALL and LGOTO to address any location of program space.

When a call or interrupt is happening, next ROM address is written to top of the stack, when RET, RETIA or RETIE instruction is executed, the top of stack data is read and load to PC.

NY8TM52D program ROM address 0x7FE~0x7FF are reserved space, if user tries to write code in these addresses will get unexpected false functions.

NY8TM52D program ROM address 0x00E~0x00F are preset rolling code can be released and used as normal program space.

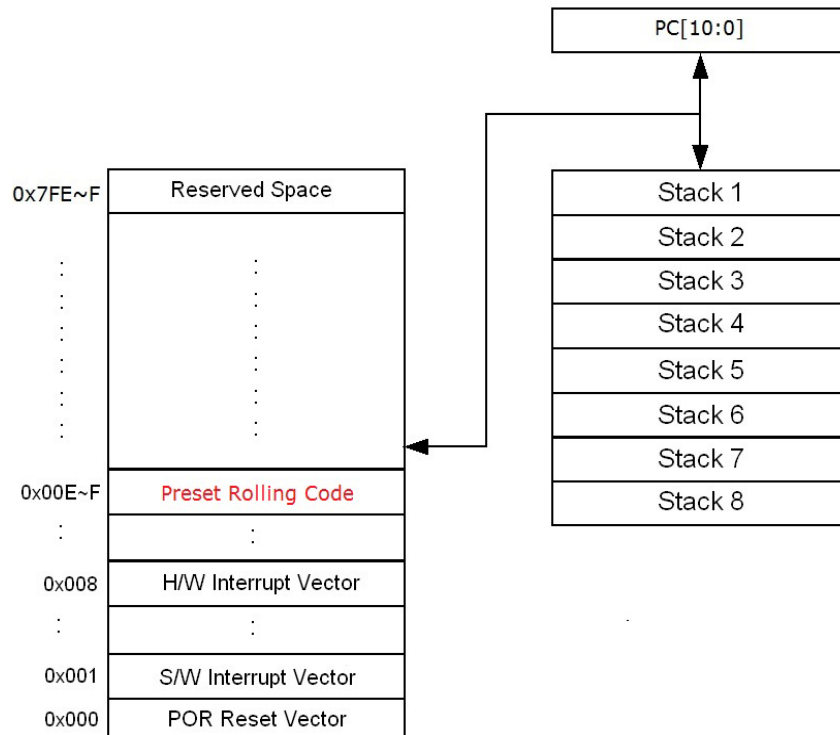


Figure 2 Program Memory Address Mapping

2.2 SRAM/Register Memory

According to instructions used to access SRAM/register memory, the memory can be divided into three kinds of categories: one is R-page Special-function Register (SFR) + General Purpose Register (GPR), another is F-page SFR, the others are S-page SFR and T-page SFR. GPR are made of SRAM and user can use them to store variables or intermediate results.

R-page data memory is divided into 4 banks and can be accessed directly or indirectly through a SFR register which is File Select Register (FSR). STATUS[7:6] are used as Bank register BK[1:0] to select one bank out of the 4 banks.

R-page register can be divided into addressing mode: direct addressing mode and indirect addressing mode.

The indirect addressing mode of data memory access is described in the following graph. This indirect addressing mode is implied by accessing register INDF. The bank selection is determined by STATUS[7:6] and the location selection is from FSR[6:0].

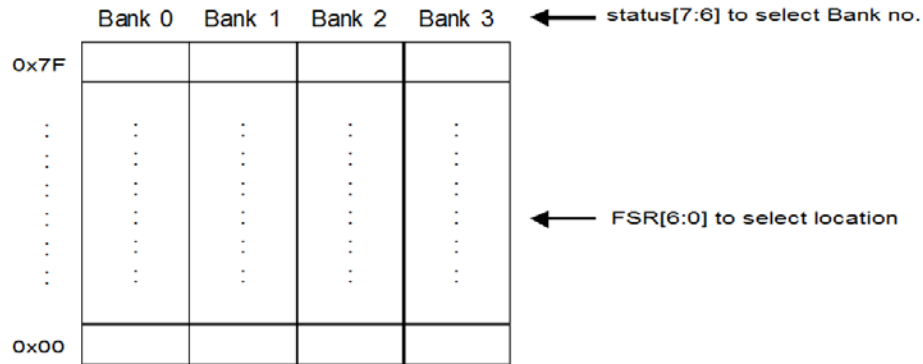


Figure 3 Indirect Addressing Mode of Data Memory Access

The direct addressing mode of data memory access is described below. The bank selection is determined by STATUS[7:6] and the location selection is from instruction op-code[6:0] immediately.

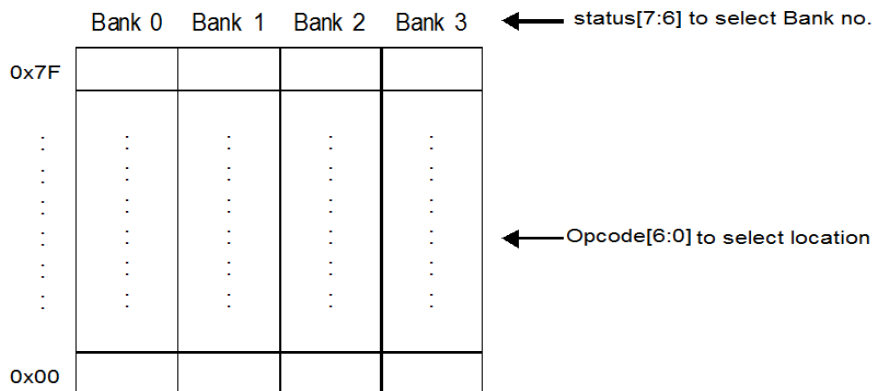


Figure 4 Direct Addressing Mode of Data Memory Access

R-page SFR can be accessed by general instructions like arithmetic instructions and data movement instructions. The R-page SFR occupy address from 0x0 to 0x1F of Bank 0. However, the same address range of Bank 1, Bank 2 and Bank 3 are mapped back to Bank 0. In other words, R-page SFR physically existed at Bank 0. The GPR physically occupy address from 0x20 to 0x7F of Bank 0 and 0x20 to 0x3F of Bank 1. Other bank in address from 0x20 to 0x7F are mapped back as the Table 1 shows..

The NY8TM52D register name and address mapping of R-page SFR are described in the following table.

FSR[7:6] Address	00 (Bank 0)	01 (Bank 1)	10 (Bank 2)	11 (Bank 3)
0x0	INDF	The same mapping as Bank 0		
0x1	TMR0			
0x2	PCL			
0x3	STATUS			
0x4	FSR			
0x5	-			
0x6	PORTB			
0x7	-			
0x8	PCON			
0x9	BWUCON			
0xA	PCHBUF			
0xB	BPLCON			
0xC	BPHCON			
0xD	-			
0xE	INTE			
0xF	INTF			
0x10 ~ 0x17	-			
0x18	INTEDG			
0x19	TMRH			
0x1A	ANAEN			
0x1B				
0x1C	PWM3RH			
0x1D ~ 0x1F	-			
0x20 ~ 0x3F	General Purpose Register	General Purpose Register	Mapped to bank0	Mapped to Bank1
0x40 ~ 0x7F	General Purpose Register	Mapped to bank0	Mapped to bank0	Mapped to bank0

Table 1 R-page SFR Address Mapping

F-page SFR can be accessed only by instructions IOST and IOSTR. S-page SFR can be accessed only by instructions SFUN and SFUNR. T-page SFR can be accessed only by instructions TFUN and TFUNR. STATUS[7:6] bank select bits are ignored while F-page and S-page register is accessed. The register name and address mapping of F-page, S-page and T-page are depicted in the following table.

SFR Category Address	F-page SFR	S-page SFR	T-page SFR
0x0	-	TMR1	
0x1	-	T1CR1	
0x2	-	T1CR2	
0x3	-	PWM1DUTY	
0x4	-	PS1CV	
0x5	-	BZ1CR	
0x6	IOSTB	IRCR	
0x7	-	TBHP	INTE3
0x8	-	TBHD	INTF3
0x9	-	-	TPCKS
0xA	PS0CV	P2CR1	CASR
0xB	-	-	TPCHS
0xC	BODCON	PWM2DUTY	TPCR
0xD	-	-	TPCNTL
0xE	CMPCR		TPCNTH
0xF	PCON1	OSCCR	TPPADEN
0x10	-	-	-
0x11	-	P3CR1	-
0x12	-	-	-
0x13	-	PWM3DUTY	-
0x14 ~ 0x1F	-	-	-

Table 2 F-page, S-page and T-page Address Mapping

3. Function Description

This chapter will describe the detailed operations of NY8TM52D.

3.1 R-page Special Function Register

3.1.1 INDF (Indirect Addressing Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
INDF	R	0x0	INDF[7:0]							
R/W Property			R/W							
Initial Value			xxxxxxx							

The register INDF is not physically existed and it is used as indirect addressing mode. Any instruction accessing INDF actually accesses the register pointed by register FSR

3.1.2 TMR0 (Timer0 Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
TMR0	R	0x1	TMR0[7:0]							
R/W Property			R/W							
Initial Value			xxxxxxx							

When read the register TMR0, it actually read the current running value of Timer0.

Write the register TMR0 will change the current value of Timer0.

Timer0 clock source can be from instruction clock F_{INST} , or from external pin EX_CK1, or from Low Oscillator Frequency according to T0MD and configuration word setting.

3.1.3 PCL (Low Byte of PC[10:0])

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
PCL	R	0x2	PCL[7:0]							
R/W Property			R/W							
Initial Value			0x00							

The register PCL is the least significant byte (LSB) of 11-bit PC. PCL will be increased by one after one instruction is executed except some instructions which will change PC directly. The high byte of PC, i.e. PC[10:8], is not directly accessible. Update of PC[10:8] must be done through register PCHBUF.

For LGOTO instruction, PC[10:0] is from instruction word.

For LCALL instruction, PC[10:0] is from instruction word. Moreover the next PC address, i.e. PC+1, will push onto top of Stack.

3.1.4 STATUS (Status Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
STATUS	R	0x3	BK[1]	BK[0]	GP5	/TO	/PD	Z	DC	C
R/W Property			R/W	R/W	R/W	R/W(*2)	R/W(*1)	R/W	R/W	R/W
Initial Value			0	0	0	1	1	X	X	X

The register STATUS contains result of arithmetic instructions and reasons to cause reset.

C: Carry/Borrow bit

C=1, carry is occurred for addition instruction or borrow is not occurred for subtraction instruction.

C=0, carry is not occurred for addition instruction or borrow is occurred for subtraction instruction.

DC: Half Carry/half Borrow bit

DC=1, carry from the 4th LSB is occurred for addition instruction or borrow from the 4th LSB is not occurred for subtraction instruction.

DC=0, carry from the 4th LSB is not occurred for addition instruction or borrow from the 4th LSB is occurred for subtraction instruction.

Z: Zero bit

Z=1, result of logical operation is zero.

Z=0, result of logical operation is not zero.

/PD: Power down flag bit

/PD=1, after power-up or after instruction CLRWDWT is executed.

/PD=0, after instruction SLEEP is executed.

/TO: Time overflow flag bit

/TO=1, after power-up or after instruction CLRWDWT or SLEEP is executed.

/TO=0, WDT timeout is occurred.

BK[1:0]: Bank register, used to select one specific bank of data ram/register.

GP5: General read/write register bits.

(*1) can be cleared by sleep instruction.

(*2) can be set by CLRWDWT instruction.

3.1.5 FSR (Register File Selection Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
FSR	R	0x4	GP7	FSR[6:0]						
R/W Property			R/W	R/W						
Initial Value			0	X	X	X	X	X	X	X

FSR[6:0]: Select one register out of 128 registers of specific Bank.

GP7: General read/write register bits.

3.1.6 PortB (PortB Data Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
PortB	R	0x6	GP7	GP6	PB5	PB4	PB3	PB2	PB1	PB0
R/W Property			R/W							
Initial Value			Data latch value is xxxxxx, read value is xxxxxx port value(PB5~PB0)							

While reading PortB, it will get the status of the specific pin if that pin is configured as input pin. However, if that pin is configured as output pin, whether it will get the status of the pin or the value of the corresponding output data latch is depend on the configuration word RD_OPT. While writing to PortB, data is written to PB's output data latch.

GP7, GP6: General purpose read/write register bit.

3.1.7 PCON (Power Control Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
PCON	R	0x8	WDTEN	GP6	LVDEN	GP4	LVREN	GP2	GP1	GP0
R/W Property			R/W							R
Initial Value			1	0	0	1	1	0	0	0

GP6,4,2,1,0: General read/write register bits.

LVREN: Enable/disable LVR.

LVREN=1, enable LVR.

LVREN=0, disable LVR.

LVDEN: Enable/disable LVD.

LVDEN=1, enable LVD.

LVDEN=0, disable LVD.

WDTEN: Enable/disable WDT.

WDTEN=1, enable WDT.

WDTEN=0, disable WDT.

3.1.8 BWUCON (PortB Wake-up Control Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
BWUCON	R	0x9	-	-	WUPB5	WUPB4	WUPB3	WUPB2	WUPB1	WUPB0
R/W Property			-	-	R/W	R/W	R/W	R/W	R/W	R/W
Initial Value			X	X	1	1	1	1	1	1

WUPBx: Enable/disable PBx wake-up function, $0 \leq x \leq 5$.

WUPBx=1, enable PBx wake-up function.

WUPBx=0, disable PBx wake-up function.

3.1.9 PCHBUF (High Byte of PC)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
PCHBUF	R	0xA	-	-	-	-	-	PCHBUF[2:0]		
R/W Property			-	-	-	-	-	R/W		
Initial Value			X	X	X	X	X	000		

PCHBUF[2:0]: Buffer of the 10th, 9th bit, 8th bit of PC.

3.1.10 BPLCON (PortB Pull-Low Resistor Control Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
BPLCON	R	0xB	/PLPB3	/PLPB2	/PLPB1	/PLPB0	-	-	-	-
R/W Property			R/W	R/W	R/W	R/W	-	-	-	-
Initial Value			1	1	1	1	X	X	X	X

/PLPBx: Disable/enable PBx Pull-Low resistor, $0 \leq x \leq 3$.

/PLPBx=1, disable PBx Pull-Low resistor.

/PLPBx=0, enable PBx Pull-Low resistor.

3.1.11 BPHCON (PortB Pull-High Resistor Control Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
BPHCON	R	0xC	-	-	/PHPB5	/PHPB4	/PHPB3	/PHPB2	/PHPB1	/PHPB0
R/W Property			-	-	R/W	R/W	R/W	R/W	R/W	R/W
Initial Value			X	X	1	1	1	1	1	1

/PHPBx: Disable/enable PBx Pull-High resistor, $0 \leq x \leq 5$.

/PHPBx=1, disable PBx Pull-High resistor.

/PHPBx=0, enable PBx Pull-High resistor.

3.1.12 INTE (Interrupt Enable Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
INTE	R	0xE	-	WDTIE	-	LVDIE	T1IE	INTIE	PBIE	T0IE
R/W Property			-	R/W	-	R/W	R/W	R/W	R/W	R/W
Initial Value			X	0	X	0	0	0	0	0

T0IE: Timer0 overflow interrupt enable bit.

T0IE=1, enable Timer0 overflow interrupt.

T0IE=0, disable Timer0 overflow interrupt.

PBIE: PortB input change interrupt enable bit.

PBIE=1, enable PortB input change interrupt.

PBIE=0, disable PortB input change interrupt.

INTIE: External interrupt enable bit.

INTIE=1, enable external interrupt.

INTIE=0, disable external interrupt.

T1IE: Timer1 underflow interrupt enable bit.

T1IE=1, enable Timer1 underflow interrupt.

T1IE=0, disable Timer1 underflow interrupt.

LVDIE: Low-voltage detector interrupt enable bit.

LVDIE=1, enable low-voltage detector interrupt.

LVDIE=0, disable low-voltage detector interrupt.

WDTIE: WDT timeout interrupt enable bit.

WDTIE=1, enable WDT timeout interrupt.

WDTIE=0, disable WDT timeout interrupt.

3.1.13 INTF (Interrupt Flag Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
INTF	R	0xF	-	WDTIF	-	LVDIF	T1IF	INTIF	PBIF	T0IF
R/W Property			-	R/W	-	R/W	R/W	R/W	R/W	R/W
Initial Value(note*)			X	0	X	0	0	0	0	0

T0IF: Timer0 overflow interrupt flag bit.

T0IF=1, Timer0 overflow interrupt is occurred.

T0IF must be clear by firmware.

PBIF: PortB input change interrupt flag bit.

PBIF=1, PortB input change interrupt is occurred.

PBIF must be clear by firmware.

INTIF: External interrupt flag bit.

INTIF=1, external interrupt is occurred.

INTIF must be clear by firmware.

T1IF: Timer1 underflow interrupt flag bit.

T1IF=1, Timer1 underflow interrupt is occurred.

T1IF must be clear by firmware.

LVDIF: Low-voltage detector interrupt flag bit.

LVDIF=1, Low-voltage detector interrupt is occurred.

LVDIF must be clear by firmware.

WDTIF: WDT timeout interrupt flag bit.

WDTIF=1, WDT timeout interrupt is occurred.

WDTIF must be clear by firmware.

Note: When corresponding *INTE* bit is not enabled, the read interrupt flag is 0.

3.1.14 INTEDG (Interrupt Edge Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
INTEDG	R	0x18	-	-	-	EIS	-	-	INTG1	INTG0
R/W Property			-	-	-	R/W	-	-	R/W	R/W
Initial Value			X	X	X	0	X	X	0	1

INTG1~0: INT edge trigger select bit.

00: reserved,

01: rising edge,

10: falling edge,

11: rising/falling edge.

EIS: External interrupt select bit

EIS=1, PB0 is external interrupt.

EIS=0, PB0 is GPIO.

3.1.15 TMRH (Timer High Byte Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
TMRH	R	0x19	-	-	TMR19	TMR18	PWM2 DUTY9	PWM2 DUTY8	PWM1 DUTY9	PWM1 DUTY8
R/W Property			-	-	R/W	R/W	R/W	R/W	R/W	R/W
Initial Value			X	X	X	X	X	X	X	X

TMR19~8: Timer1 MSB 2 bits. Write these 2 bits will overwrite the 10-bit Timer1 load value of bit 9 and 8.

Read these 2 bits will get the Timer1 bit9-8 current value.

PWM1DUTY9~8: PWM1 duty data MSB 2 bits.

PWM2DUTY9~8: PWM2 duty data MSB 2 bits.

3.1.16 ANAEN (Analog Circuit Enable Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
ANAEN	R	0x1A	CMPEN	-	-	-	-	-	-	-
R/W Property			R/W	-	-	-	-	-	-	-
Initial Value			0	0	X	X	X	X	X	X

CMPEN: Enable/disable voltage comparator.

CMPEN=1, enable voltage comparator.

CMPEN=0, disable voltage comparator.

3.1.17 PWM3RH (PWM3DUTY High Byte Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
PWM3RH	R	0x1C	-	-	-	-	-	-	PWM3DUTY9	PWM3DUTY8
R/W Property			-	-	-	-	-	-	R/W	R/W
Initial Value			X	X	X	X	X	X	X	X

PWM3DUTY9~8: PWM3 duty data MSB 2 bits.

3.2 T0MD Register

T0MD is a readable/writeable register which is only accessed by instruction T0MD / T0MDR.

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
T0MD	-	-	LCKTM0	GP6	T0CS	T0CE	PS0WDT	PS0SEL[2:0]		
R/W Property			R/W							
Initial Value(note*)			0	0	1	1	1	111		

PS0SEL[2:0]: Prescaler0 dividing rate selection. The rate depends on Prescaler0 is assigned to Timer0 or WDT. When Prescaler0 is assigned to WDT, the dividing rate is dependent on which timeout mechanism is selected.

PS0SEL[2:0]	Dividing Rate		
	PS0WDT=0 (Timer0)	PS0WDT=1 (WDT Reset)	PS0WDT=1 (WDT Interrupt)
000	1:2	1:1	1:2
001	1:4	1:2	1:4
010	1:8	1:4	1:8
011	1:16	1:8	1:16
100	1:32	1:16	1:32
101	1:64	1:32	1:64
110	1:128	1:64	1:128
111	1:256	1:128	1:256

Table 3 Prescaler0 Dividing Rate

PS0WDT: Prescaler0 assignment.

PS0WDT=1, Prescaler0 is assigned to WDT.

PS0WDT=0, Prescaler0 is assigned to Timer0.

Note: Always set PS0WDT and PS0SEL[2:0] before enabling watchdog or timer interrupt, or reset or interrupt may be falsely triggered.

T0CE: Timer0 external clock edge selection.

T0CE=1, Timer0 will increase one while high-to-low transition occurs on pin EX_CK1.

T0CE=0, Timer0 will increase one while low-to-high transition occurs on pin EX_CK1.

Note: T0CE is also applied to Low Oscillator Frequency as timer0 clock source condition.

T0CS: Timer0 clock source selection.

T0CS=1, External clock on pin EX_CK1 or Low Oscillator Frequency (I_LRC) is selected.

T0CS=0, Instruction clock F_{INST} is selected.

LCKTM0: When T0CS=1, timer 0 clock source can be optionally selected to be low-frequency oscillator.

T0CS=0, Instruction clock F_{INST} is selected as timer0 clock source.

T0CS=1, LCKTM0=0, external clock on pin EX_CK1 is selected as timer0 clock source.

T0CS=1, LCKTM0=1, Low Oscillator Frequency (I_LRC) output replaces pin EX_CK1 as timer0 clock source.

GP6: General read/write register bit.

Note: For more detail descriptions of timer0 clock source select, please see timer0 section.

3.3 F-page Special Function Register

3.3.1 IOSTB (PortB I/O Control Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
IOSTB	F	0x6	-	-	IOPB5	IOPB4	IOPB3	IOPB2	IOPB1	IOPB0
R/W Property			-	-	R/W	R/W	R/W	R/W	R/W	R/W
Initial Value			X	X	1	1	1	1	1	1

IOPBx: PBx I/O mode selection, $0 \leq x \leq 5$.

IOPBx=1, PBx is input mode.

IOPBx=0, PBx is output mode.

3.3.2 PS0CV (Prescaler0 Counter Value Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
PS0CV	F	0xA	PS0CV[7:0]							
R/W Property			R							
Initial Value			1	1	1	1	1	1	1	1

While reading PS0CV, it will get current value of Prescaler0 counter.

3.3.3 BODCON (PortB Open-Drain Control Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
BODCON	F	0xC	GP7	GP6	ODPB5	ODPB4	ODPB3	ODPB2	ODPB1	ODPB0

R/W Property	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Initial Value	0	0	0	0	0	0	0	0

ODPBx: Enable/disable open-drain of PBx, $0 \leq x \leq 5$.

ODPBx=1, enable open-drain of PBx.

ODPBx=0, disable open-drain of PBx.

GP7~6: General purpose register bit.

3.3.4 CMPCR (Comparator voltage select Control Register)

Name	SFR Type	Addr	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
CMPCR	F	0xE	-	RBIAS_H	RBIAS_L	CMP_INV	PS1	PS0	NS1	NS0
R/W Property				R/W						
Initial Value			0	0	0	0	1	1	0	0

NS[1:0]: Comparator inverting input select.

NS[1:0]	Inverting input
00	PB2
01	PB5
10	Bandgap (0.6V)
11	Vref

PS[1:0]: Comparator non-inverting input select

PS[1:0]	Non-inverting input
00	PB0
01	PB4
10	Vref
11	---

CMPF_INV: Comparator output inverse control bit.

CMPF_INV = 1, Inverse comparator output.

CMPF_INV = 0, Non-inverse comparator output.

RBIAS_L, RBIAS_H: Set corresponding voltage reference levels

3.3.5 PCON1 (Power Control Register1)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
PCON1	F	0xF	GIE	LVDOOUT	LVDS3	LVDS2	LVDS1	LVDS0	GP1	T0EN
R/W Property			R/W ^(1*)	R	R/W	R/W	R/W	R/W	R/W	R/W
Initial Value			0	X	0	1	1	1	0	1

T0EN: Enable/disable Timer0.

T0EN=1, enable Timer0.

T0EN=0, disable Timer0.

GIE: Global interrupt enable bit.

GIE=1, enable all unmasked interrupts.

GIE=0, disable all interrupts.

GP1: General purpose register bit.

(1*) : set by instruction ENI, clear by instruction DISI, read by instruction IOSTR.

LVDOOUT : Low voltage detector output, read-only.

LVDS3~0 : Select LVD voltage.

LVDS[3:0]	Voltage
0000	1.9V
0001	2.0V
0010	2.2V
0011	2.4V
0100	2.6V
0101	2.8V
0110	2.9V
0111	3.0V
1000	3.15V
1001	3.30V
1010	3.45V
1011	3.60V
1100	3.75V
1101	3.90V
1110	4.05V
1111	4.15V

Table 4 LVD voltage select

3.4 S-page Special Function Register

3.4.1 TMR1 (Timer1 Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
TMR1	S	0x0	TMR1[7:0]							
R/W Property			R/W							
Initial Value			XXXXXXXX							

When reading register TMR1, it will obtain current value of 10-bit down-count Timer1 at TMR1[9:0]. When writing register TMR1, it will write data from TMRH[5:4] and Timer1 reload register to TMR1[9:0] current content.

3.4.2 T1CR1 (Timer1 Control Register1)

Name	SFR Type	Addr	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
T1CR1	S	0x1	PWM1OEN	PWM1OAL	-	-	-	T1OS	T1RL	T1EN
R/W Property			R/W	R/W	-	-	-	R/W	R/W	R/W
Initial Value			0	0	X	X	X	0	0	0

This register is used to configure Timer1 functionality.

T1EN: Enable/disable Timer1.

T1EN=1, enable Timer1.

T1EN=0, disable Timer1.

T1RL: Configure Timer1 down-count mechanism while Non-Stop mode is selected (T1OS=0).

T1RL=1, initial value is reloaded from reload register TMR1[9:0].

T1RL=0, continuous down-count from 0x3FF when underflow is occurred.

T1OS: Configure Timer1 operating mode while underflow is reached.

T1OS=1, One-Shot mode. Timer1 will count once from the initial value to 0x00.

T1OS=0, Non-Stop mode. Timer1 will keep down-count after underflow.

T1OS	T1RL	Timer1 Down-Count Functionality
0	0	Timer1 will count from reload value down to 0x00. When underflow is reached, 0x3FF is reloaded and continues down-count.
0	1	Timer1 will count from reload value down to 0x00. When underflow is reached, reload value is reloaded and continues to down-count.
1	x	Timer1 will count from initial value down to 0x00. When underflow is reached, Timer1 will stop down-count.

Table 5 Timer1 Functionality

PWM1OAL: Define PWM1 output active state.

PWM1OAL=1, PWM1 output is active low.

PWM1OAL=0, PWM1 output is active high.

PWM1OEN: Enable/disable PWM1 output.

PWM1OEN=1, PWM1 output will be present on PB2.

PWM1OEN=0, PB2 is GPIO.

3.4.3 T1CR2 (Timer1 Control Register2)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
T1CR2	S	0x2	-	-	T1CS	T1CE	/PS1EN	PS1SEL[2:0]		
R/W Property			-	-	R/W	R/W	R/W	R/W	R/W	R/W
Initial Value			X	X	1	1	1	1	1	1

This register is used to configure Timer1 functionality.

PS1SEL[2:0]: Prescaler1 dividing rate selection.

PS1SEL[2:0]	Dividing Rate
000	1:2
001	1:4
010	1:8
011	1:16
100	1:32
101	1:64
110	1:128
111	1:256

Table 6 Prescaler1 Dividing Rate

Note: Always set PS1SEL[2:0] at /PS1EN=1, or interrupt may be falsely triggered.

/PS1EN: Disable/enable Prescaler1.

/PS1EN=1, disable Prescaler1.

/PS1EN=0, enable Prescaler1.

T1CE: Timer1 external clock edge selection.

T1CE=1, Timer1 will decrease one while high-to-low transition occurs on pin EX_CK1.

T1CE=0, Timer1 will decrease one while low-to-high transition occurs on pin EX_CK1.

T1CS: Timer1 clock source selection.

T1CS=1, External clock on pin EX_CK1 is selected.

T1CS=0, Instruction clock is selected.

3.4.4 PWM1DUTY (PWM1 Duty Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
PWM1DUTY	S	0x3	PWM1DUTY[7:0]							
R/W Property			W							
Initial Value			XXXXXXXX							

The reload value of 10-bit Timer1 stored on registers TMRH[5:4] and TMR1[7:0] is used to define the PWM1 frame rate, and registers TMRH[1:0] and PWM1DUTY[7:0] is used to define the duty cycle of PWM1.

3.4.5 PS1CV (Prescaler1 Counter Value Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
PS1CV	S	0x4	PS1CV[7:0]							
R/W Property			R							
Initial Value			1	1	1	1	1	1	1	1

While reading PS1CV, it will get current value of Prescaler1 counter.

3.4.6 BZ1CR (Buzzer1 Control Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
BZ1CR	S	0x5	BZ1EN	-	-	-	BZ1FSEL[3:0]			
R/W Property			W	-	-	-	W			
Initial Value			0	X	X	X	1	1	1	1

BZ1FSEL[3:0]:Frequency selection of BZ1 output.

BZ1FSEL[3:0]	BZ1 Frequency Selection	
	Clock Source	Dividing Rate
0000	Prescaler1 output	1:2
0001		1:4
0010		1:8
0011		1:16
0100		1:32
0101		1:64
0110		1:128
0111		1:256
1000	Timer1 output	Timer1 bit 0
1001		Timer1 bit 1
1010		Timer1 bit 2
1011		Timer1 bit 3
1100		Timer1 bit 4

BZ1FSEL[3:0]	BZ1 Frequency Selection	
	Clock Source	Dividing Rate
1101		Timer1 bit 5
1110		Timer1 bit 6
1111		Timer1 bit 7

Table 7 Buzzer1 Output (PB2) Frequency Selection

BZ1EN: Enable/Disable BZ1 output.

BZ1EN=1, enable Buzzer1.

BZ1EN=0, disable Buzzer1.

3.4.7 IRCR (IR Control Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
IRCR	S	0x6	-	-	-	-	-	IRCSEL	IRF57K	IREN
R/W Property			-	-	-	-	-	W	W	W
Initial Value			X	X	X	X	X	0	0	0

IREN: Enable/Disable IR carrier output.

IREN=1, enable IR carrier output.

IREN=0, disable IR carrier output.

IRF57K: Selection of IR carrier frequency.

IRF57K=1, IR carrier frequency is 57K mode.

IRF57K=0, IR carrier frequency is 38K mode.

IRCSEL: Polarity selection of IR carrier.

IRCSEL=0, IR carrier will be generated when I/O pin data is 1.

IRCSEL=1, IR carrier will be generated when I/O pin data is 0.

Note:

1. Only high oscillation (F_{Hosc}) (See section 3.14) can be used as IR clock source.

2. IRF57K=1, IR carrier frequency is $4\text{MHz}/64 = 62.5\text{KHz}$.

OSC. Type	57KHz	38KHz	Conditions
High IRC(4MHz)	64	96	HIRC mode (the input to IR module is set to 4MHz no matter what system clock is)

Table 8 Division ratio for different oscillation type

3.4.8 TBHP (Table Access High Byte Address Pointer Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
TBHP	S	0x7	-	-	-	-	-	TBHP2	TBHP1	TBHP0
R/W Property			-	-	-	-	-	R/W	R/W	R/W

Initial Value	X	X	X	X	X	X	X	X
---------------	---	---	---	---	---	---	---	---

When instruction CALLA, GOTOA or TABLEA is executed, the target address is constituted by TBHP[2:0] and ACC. ACC is the Low Byte of PC[10:0] and TBHP[2:0] is the high byte of PC[10:0]. ~~GP2 is general register for NY8TM52D.~~

3.4.9 TBHD (Table Access High Byte Data Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
TBHD	S	0x8	-	-	TBHD5	TBHD4	TBHD3	TBHD2	TBHD1	TBHD0
R/W Property			-	-	R	R	R	R	R	R
Initial Value			X	X	X	X	X	X	X	X

When instruction TABLEA is executed, high byte of content of addressed ROM is loaded into TBHD[5:0] register. The Low Byte of content of addressed ROM is loaded to ACC.

3.4.10 P2CR1 (PWM2 Control Register1)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
P2CR1	S	0xA	PWM2OEN	PWM2OAL	-	-	TM1HRC	-	-	-
R/W Property			R/W	R/W	-	-	R/W	-	-	-
Initial Value			0	0	X	X	0	X	X	X

This register is used to configure PWM2 functionality.

TM1_HRC: Timer1 clock source selection.

TM1HRC=1, PWM1, 2, 3 & Timer 1 clock source is High Oscillator clock.

TM1HRC=0, PWM1, 2, 3 & Timer 1 clock source selection depends on T1CS register bit,

PWM2OAL: Define PWM2 output active state.

PWM2OAL=1, PWM2 output is active low.

PWM2OAL=0, PWM2 output is active high.

PWM2OEN: Enable/disable PWM2 output.

PWM2OEN=1, PWM2 output will be present on PB0.

3.4.11 PWM2DUTY (PWM2 Duty Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
PWM2DUTY	S	0xC	PWM2DUTY[7:0]							
R/W Property			W							
Initial Value			XXXXXXXX							

The reload value of 10-bit Timer1 stored on registers TMRH[5:4] and TMR1[7:0] is used to define the PWM2 frame rate, and registers TMRH[3:2] and PWM2DUTY[7:0] is used to define the duty cycle of PWM2.

3.4.12 OSCCR (Oscillation Control Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
OSCCR	S	0xF	-	CMPOE	-	-	OPMD[1:0]	STPHOSC	SELHOSC	
R/W Property			-	R/W	-	-	R/W	R/W	R/W	
Initial Value			X	0	X	X	00	0	1	

CMPOE: Compare Output Enable

CMPOE=1, PB3 is compare out.

CMPOE=0, PB3 is I/O.

SELHOSC: Selection of system oscillation (F_{osc}).

SELHOSC=1, F_{osc} is high-frequency oscillation (F_{Hosc}).

SELHOSC=0, F_{osc} is low-frequency oscillation (F_{Losc}).

STPHOSC: Disable/enable high-frequency oscillation (F_{Hosc}).

STPHOSC=1, F_{Hosc} will stop oscillation and be disabled.

STPHOSC=0, F_{Hosc} keep oscillation.

OPMD[1:0]: Selection of operating mode.

OPMD[1:0]	Operating Mode
00	Normal mode
01	Halt mode
10	Standby mode
11	reserved

Table 9 Selection of Operating Mode by OPMD[1:0]

Note: STPHOSC cannot be changed with SELHOSC or OPMD at the same time. STPHOSC cannot be changed with OPMD at the same time during SELHOSC=1.

3.4.13 P3CR1 (PWM3 Control Register1)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
P3CR1	S	0x11	PWM3OEN	PWM3OAL	-	-	-	-	-	-
R/W Property			R/W	R/W	-	-	-	-	-	-
Initial Value			0	0	X	X	X	X	X	X

This register is used to configure PWM3 functionality.

PWM3OAL: Define PWM3 output active state.

PWM3OAL=1, PWM3 output is active low.

PWM3OAL=0, PWM3 output is active high.

PWM3OEN: Enable/disable PWM3 output.

PWM3OEN=1, PWM3 output will be present on PB3.

3.4.14 PWM3DUTY (PWM3 Duty Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
PWM3DUTY	S	0x13	PWM3DUTY[7:0]							
R/W Property			W							
Initial Value			XXXXXXXX							

The reload value of 10-bit Timer1 stored on registers TMRH[5:4] and TMR1[7:0] is used to define the PWM3 frame rate, and registers PWM3RH[1:0] and PWM3DUTY[7:0] is used to define the duty cycle of PWM3.

3.5 T-page Special Function Register

3.5.1 INTE3 (Interrupt Enable 3th Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
INTE3	T	0x7	GP7	-	-	-	-	-	TPOVIE	TPCPIE
R/W Property			R/W	-	-	-	-	-	R/W	R/W
Initial Value			0	0	0	0	0	0	0	0

GP7: General purpose register bit

TPOVIE: Touch pad counter overflow interrupt enable bit

1 = enable Touch pad counter overflow interrupt

0 = disable Touch pad counter overflow interrupt

TPCPIE: Touch pad compare completely interrupt enable bit

1 = enable Touch pad compare completely interrupt

0 = disable Touch pad compare completely interrupt

3.5.2 INTF3 (Interrupt Flag 3th Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
INTF3	T	0x8	-	-	-	-	-	-	TPOVIF	TPCPIF
R/W Property			-	-	-	-	-	-	R/W	R/W
Initial Value			0	0	0	0	0	0	0	0

TPOVIF: Touch pad counter overflow interrupt Flag bit

1 = Touch pad counter overflow interrupt is occurred

0 = Touch pad counter overflow interrupt is not occurred

TPCPIF: Touch pad compare completely interrupt Flag bit

1 = Touch pad compare completely interrupt is occurred

0 = Touch pad compare completely interrupt is not occurred

Write TPCR or TPCHS, will clear TPOVIF and TPCPIF.

3.5.3 TPCKS (Touch pad clock register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
TPCKS	T	0x9	-	-	-	WKUPT	-	TPCK2	TPCK1	TPCK0
R/W Property			-			R/W		R/W		
Initial Value			0	0	0	0	0	0	1	0

WKUPT: Touch slow mode wakeup period select

1= 16Hz (64ms)

0= 32Hz (32ms)

TPCK2~TPCK0: touch pad modulation clock select

100: 1.12MHz

011: 1.31MHz

010: 1MHz

001: 0.88MHz

000: 0.75MHz

3.5.4 CASR (Touch pad extra capacitance select register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
TPCAXS	T	0xA	-	CA[6:0]						
R/W Property				R/W						
Initial Value			0	0	0	0	0	0	0	0

CA6~CA0: extra capacitance select

1111 1111 : 127°C array unit

1111 1110 : 126°C array unit

0000 0001: 1°C array unit

0000 0000: 0°C array unit

Note : C array unit = ~~0.45p~~0.05pF

3.5.5 TPCHS (Touch pad channel select register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
TPCHS	T	0xB	-	-	-	-	-	CHS2	CHS1	CHS0
R/W Property			-	-				R/W		
Initial Value			0	0	0	0	0	0	0	0

CHS2~CHS0: touch pad channel select

111= select all touch pad

110= select INKEY
100~101: reserved
011 = select pad TP3
010 = select pad TP2
001 = select pad TP1
000 = select pad TP0

3.5.6 TPCR (Touch pad control register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
TPCR	T	0xC	-	-	-	-	-	TPMD2	TPMD1	TPMD0
R/W Property			-					R/W		
Initial Value			X	X	X	X	X	0	0	0

TPMD2~TPMD0 (Touch pad operation mode)

111~110: reserved
101: TPRUN in TP slow mode (Scan the channel with TPCHS select)
100 = reserved
011 = Initialize (Discharge Cs)
010 = TPCHOFF (All channel not select)
001 = TPRUN (Scan the channel which TPCHS select).
000 = TPSTP (Touch pad all stop)

When change Touch key or at TP slow mode clear TPINT flag (TPOVIF, TPCPIF), then TPMD will return to TPCHOFF mode.

3.5.7 TPCNTL (Touch pad low counter register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
TPCNTL	T	0xD	TPCNT7	TPCNT6	TPCNT5	TPCNT4	TPCNT3	TPCNT2	TPCNT1	TPCNT0
R/W Property			R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Initial Value			1	1	1	1	1	1	1	1

R: Touch counter low byte data

W: Pre-load Touch counter low byte data

3.5.8 TPCNTH (Touch pad high counter register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
TPCNTH	T	0xE	-	-	-	-	TPCNT11	TPCNT10	TPCNT9	TPCNT8
R/W Property			-				R/W	R/W	R/W	R/W
Initial Value			X	X	X	X	1	1	1	1

R: Touch counter high byte data

W: Pre-load Touch counter high byte data

TPCNT<11:0>: when address is read, the data is touch pad counter value

When address is write, the data will be 1's complement write to pre-load data value

3.5.8 TPPADEN (Touch pad enable register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
TPPADEN	T	0xF	-	-	-	-	TP3EN	TP2EN	TP1EN	TP0EN
R/W Property			-				R/W	R/W	R/W	R/W
Initial Value			X	X	X	X	0	0	0	0

TPPADEN<3:0>: I/O is Touch pad or not

TP0EN=1 PB0 act as TP0, TPEN0=0 PB0 is I/O.

TP1EN=1 PB2 act as TP1, TPEN1=0 PB2 is I/O

TP2EN=1 PB4 act as TP2, TPEN2=0 PB4 is I/O

TP3EN=1 PB5 act as TP3, TPEN3=0 PB5 is I/O

3.6 I/O Port

NY8TM52D provide 6 I/O pins which are PB[5:0]. User can read/write these I/O pins through register PORTB. Each I/O pin has a corresponding register bit to define it is input pin or output pin. Register IOSTB[5:0] define the input/output direction of PB[5:0].

When an I/O pin is configured as input pin, it may have Pull-High resistor or Pull-Low resistor which is enabled or disabled through registers. Register BPHCON[5:0] are used to enable or disable Pull-High resistor of PB[5:0]. Register BPLCON[7:4] are used to enable or disable Pull-Low resistor of PB[3:0].

When an I/O pin is configured as output pin, there is a corresponding and individual register to select as Open-Drain output pin. Register BODCON[5:0] determine PB[5:0] is Open-Drain or not.

The summary of Pad I/O feature is listed in the table below.

Feature		PB[3:0]	PB[5:4]
Input	Pull-High Resistor	V	V
	Pull-Low Resistor	V	X
Output	Open-Drain	V	V

Table 10 Summary of Pad I/O Feature

The level change on each I/O pin of PB may generate interrupt request. Register BWUCON[5:0] will select which I/O pin of PB may generate this interrupt. As long as any pin of PB is selected by corresponding bit of BWUCON, the register bit PBIF (INTF[1]) will set to 1 if there is a level change occurred on any selected pin. An interrupt request will occur and interrupt service routine will be executed if register bit PBIE (INTE[1]) and GIE (PCON1[7]) are both set to 1.

There is one external interrupt provided by NY8TM52D. When register bit EIS (INTEDG[4]) is set to 1, PB0 is used as input pin for external interrupt.

Note: When PB0 is both set as level change operation and external interrupt, the external interrupt will have higher priority, and the PB0 level change operation will be disabled. But PB5~PB1 level change function are not affected.

NY8TM52D can provide IR carrier generation. IR carrier generation is enabled by register bit IREN (IRCR[0]) and carrier will be present on a PB3 pin.

PB3 can be used as external reset input determined by a configuration word. When an active-low signal is applied to PB3, it will cause NY8TM52D to enter reset process.

When NY8TM52D is in Normal mode or Standby mode, instruction clock is observable on PB4 if a configuration word is enabled.

Moreover, PB5 can be timer 0 external clock source EX_CK1 if T0MD T0CS=1 and LCK_TM0=0. PB5 can be timer 1 external clock source if T1CS=1.

Moreover, PB2 can be PWM output if T1CR1[7] PWM1OEN=1 and corresponding PB.2 configuration word. PB2 can also be Buzzer output if BZ1CR[7] BZ1EN=1 and corresponding PB.2 configuration word.

3.6.1 Block Diagram of IO Pins

IO_SEL: set pad attribute as input or output.

WRITE_EN: write data to pad.

READ_EN: read pad.

OD_EN: enable open-Drain.

PULLUP_ENB: enable Pull-High.

PULLDOWN_EN: enable Pull-Low.

RD_TYPE: select read pin or read latch.

SFEN: Special-function enable (PWM2)

SFDT: Special-function data.

EIS: external interrupt function enable.

INTEDGE: external interrupt edge select.

EX_INT: external interrupt signal.

WUB: port B wake-up enable.

SET_PBIF: port B wake-up flag.

CMPEN: enable pad to comparator input.

TPEN: enable pad to Touch Key input.

CMPVP: comparator non-inverting.

TPIN: Touch Key input

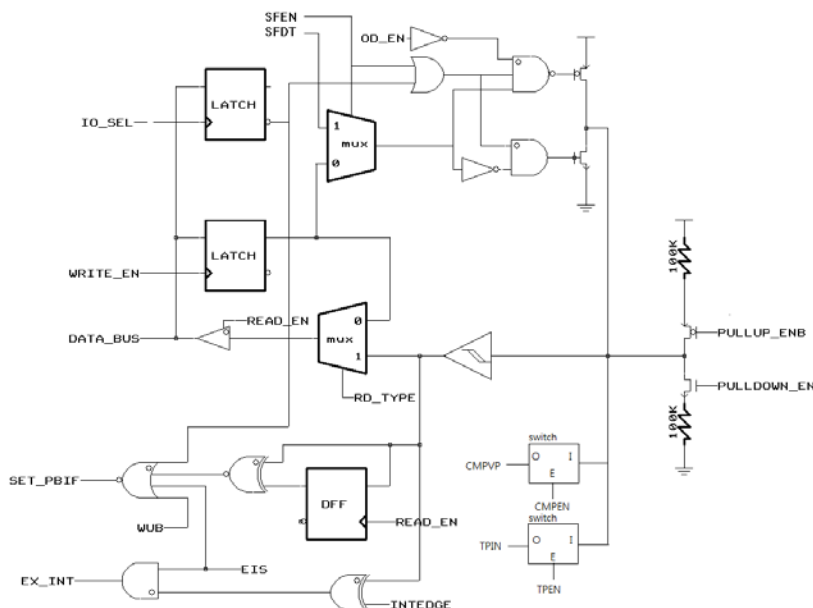


Figure 5 Block Diagram of PB0

IO_SEL: set pad attribute as input or output.

WRITE_EN: write data to pad.

READ_EN: read pad.

OD_EN: enable open-Drain.

PULLUP_ENB: enable Pull-High.

PULLDOWN_EN: enable Pull-Low.

RD_TYPE: select read pin or read latch.

SFEN: Special-function enable (IR)

SFDT: Special-function data.

WUB: port B wake-up enable.

SET_PBIF: port B wake-up flag.

CAP_EN: enable pad to external capacitor.

INITIAL: Discharge capacitor

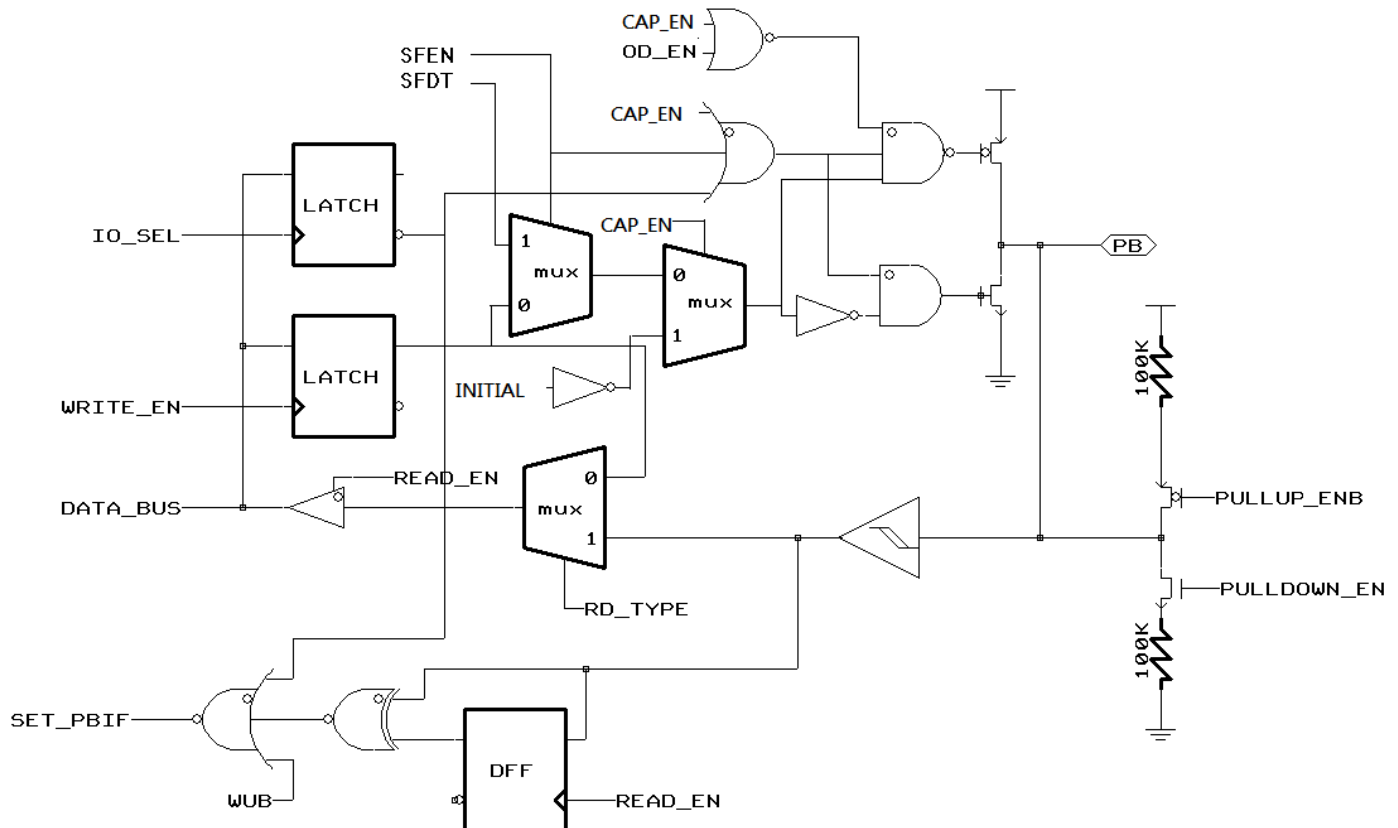


Figure 6 Block Diagram of PB1

IO_SEL: set pad attribute as input or output.

WRITE_EN: write data to pad.

READ_EN: read pad.

OD_EN: enable open-Drain.

PULLUP_ENB: enable Pull-High.

PULLDOWN_EN: enable Pull-Low.

RD_TYPE: select read pin or read latch.

SFEN: Special-function enable (PMW1/BUZZER1) .

SFDT: Special-function data data.

WUB: port B wake-up enable.

SET_PBIF: port B wake-up flag.

EX CKI: external clock input.

CMPEN: enable pad to comparator input.

TPEN: enable pad to Touch Key input.

CMPVP: comparator non-inverting.

TPIN: Touch Key input

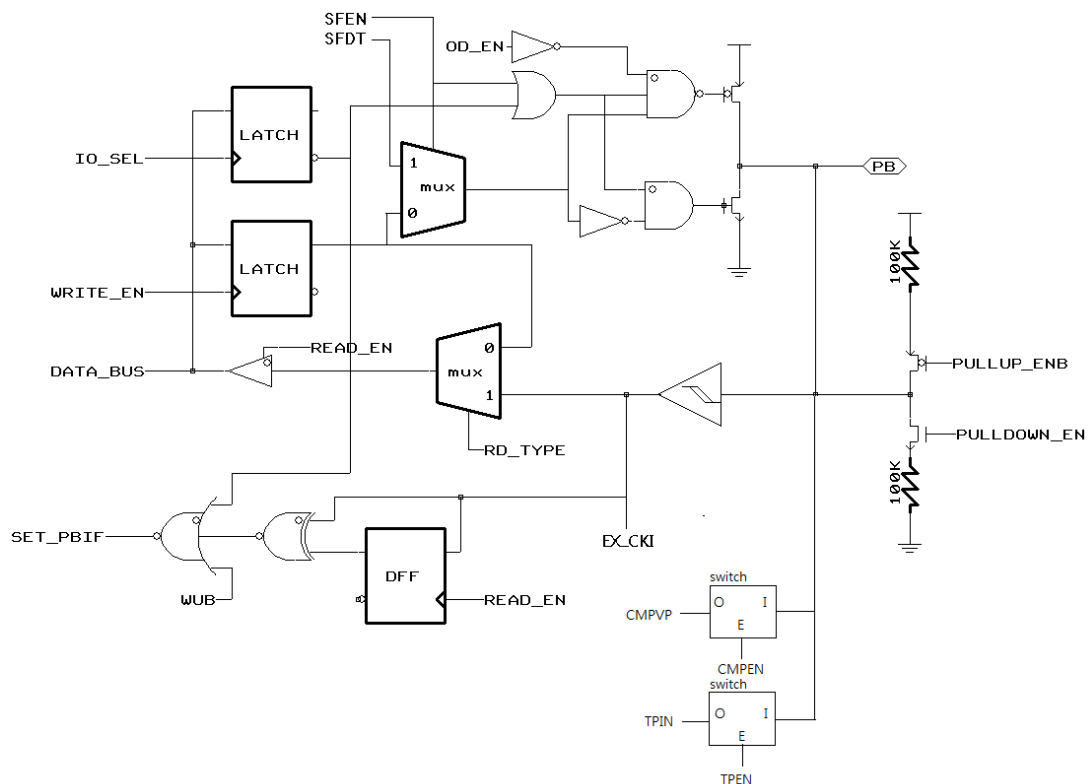


Figure 7 Block Diagram of PB2

IO_SEL: set pad attribute as input or output.

WRITE_EN: write data to pad.

READ_EN: read pad.

RSTPAD_EN: reset pad enable.

RSTB_IN: reset pad input.

PULLUP_ENB: enable Pull-High.

PULLDOWN_EN: enable Pull-Low.

RD_TYPE: select read pin or read latch.

WUB: port B wake-up enable.

SET_PBIF: port B wake-up flag.

CMPOE: enable pad to comparator output

PCON1[6]: comparator output.

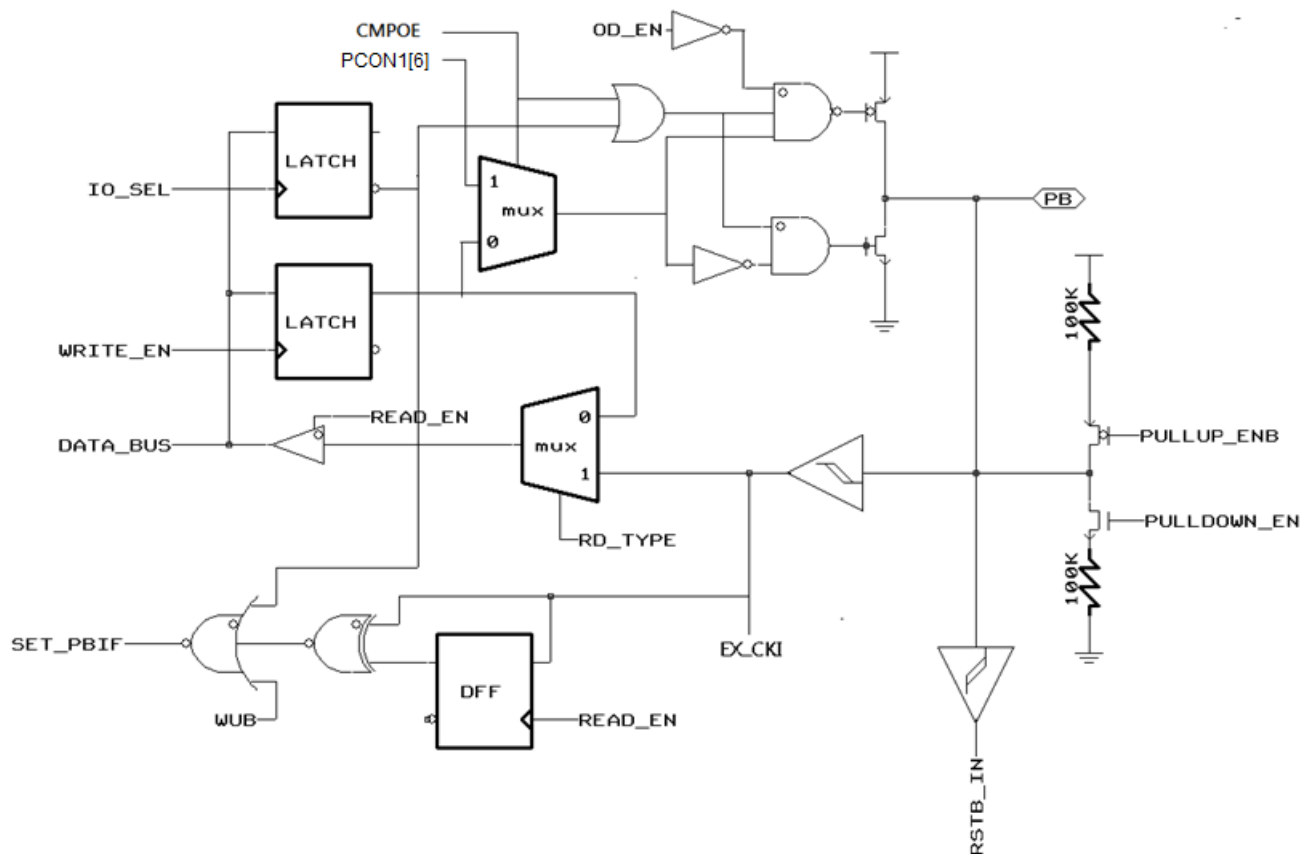


Figure 8 Block Diagram of PB3

IO_SEL: set pad attribute as input or output.

WRITE_EN: write data to pad.

READ_EN: read pad.

OD_EN: enable open-Drain.

PULLUP_ENB: enable Pull-High.

RD_TYPE: select read pin or read latch.

WUB: port B wake-up enable.

SET_PBIF: port B wake-up flag.

CMPEN: enable pad to comparator input.

TPEN: enable pad to Touch Key input.

CMPVN: comparator inverting.

TPIN: Touch Key input

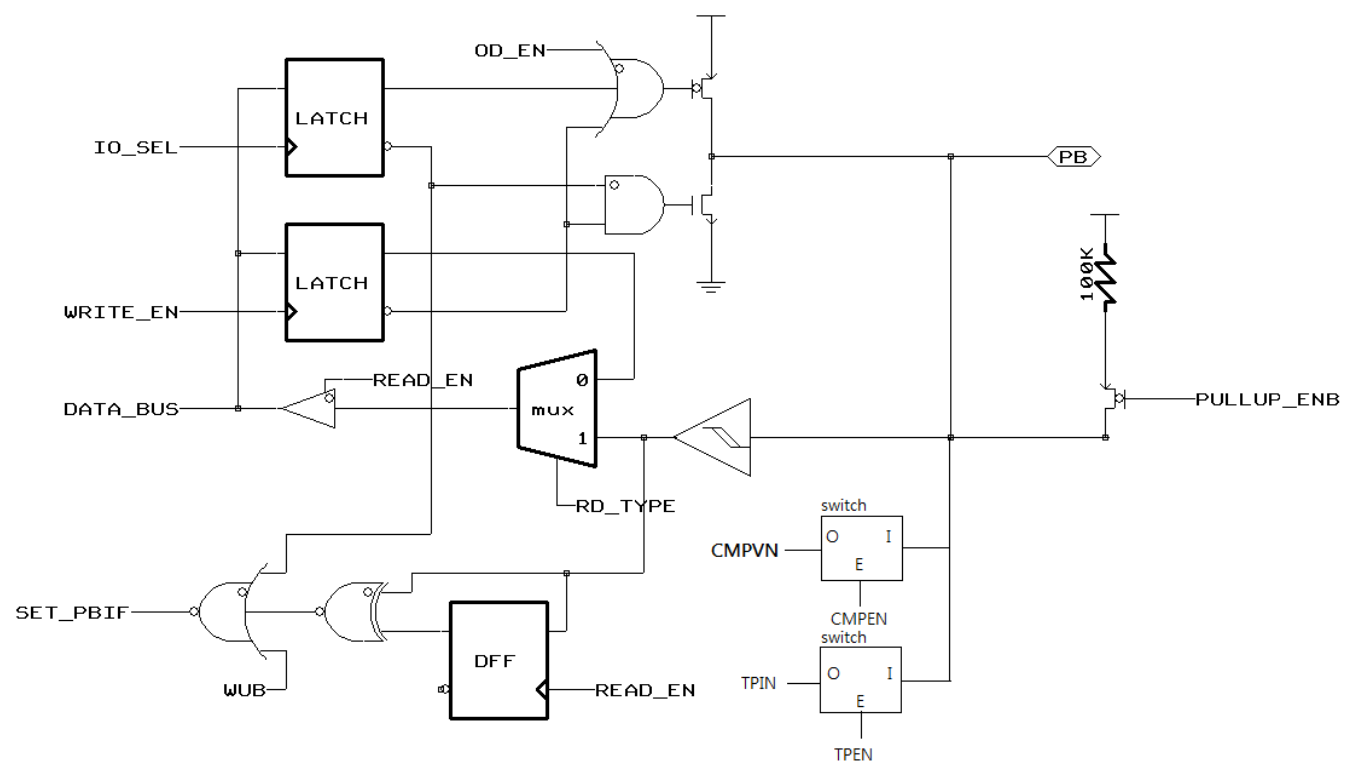


Figure 9 Block Diagram of PB4/PB5

3.7 Timer0

Timer0 is an 8-bit up-count timer and its operation is enabled by register bit T0EN (PCON1[0]). Writing to Timer0 will set its initial value. Reading from Timer0 will show its current count value.

The clock source to Timer0 can be from instruction clock, external pin EX_CK1 or low speed clock Low Oscillator Frequency according to register bit T0CS and LCK_TM0 (T0MD[5] and T0MD[7]). When T0CS is 0, instruction clock is selected as Timer0 clock source. When T0CS is 1 and LCK_TM0 is 0, EX_CK1 is selected as Timer0 clock source. When T0CS is 1 and LCK_TM0 is 1 (and Timer0 source must set to 1), Low Oscillator Frequency (I_LRC) output is selected. Summarized table is shown below. (Also check Table 10)

Timer0 clock source	T0CS	LCKTM0	Timer0 source
Instruction clock	0	X	X
EX_CK1	1	0	X
		X	0
I_LRC	1	1	1

Table 11 Summary of Timer0 clock source control

Moreover the active edge of EX_CK1 or Low Oscillator Frequency to increase Timer0 can be selected by register bit T0CE (T0MD[4]). When T0CE is 1, high-to-low transition on EX_CK1 or Low Oscillator Frequency will increase Timer0. When T0CE is 0, low-to-high transition on EX_CK1 or Low Oscillator Frequency will increase Timer0.

Before Timer0 clock source is supplied to Timer0, it can be divided by Prescaler0 if register bit PS0WDT (T0MD[3]) is clear to 0. When writing 0 to PS0WDT by instruction, Prescaler0 is assigned to Timer0 and Prescaler0 will be clear after this instruction is executed. The dividing rate of Prescaler0 is determined by register bits PS0SEL[2:0] which is from 1:2 to 1:256.

Before entering Timer0, the Timer0 clock source synchronize with instruction clock in default. If EX_CK1 or Low Oscillator Frequency is used as Timer0 clock source, care must be taken that their frequency can not exceed instruction clock frequency, or missing count may happen. When Low Oscillator Frequency is both used as Timer0 clock source and instruction clock, NY8TM52D must assign prescaler0 to Timer0 and the prescaler0 dividing ratio must be no less than 4. There's a configuration word (EX_CK1 to Inst. Clock) which can relieve this constraint. When this option is set to Async, the Timer0 clock source does not synchronize with the instruction clock, so the input frequency of EX_CK1 can be higher than the instruction clock. The maximum frequency the EX_CK1 can input is depended on process variation.

When Timer0 is overflow, the register bit T0IF (INTF[0]) will be set to 1 to indicate Timer0 overflow event is occurred. If register bit T0IE (INTE[0]) and GIE are both set to 1, interrupt request will occur and interrupt service routine will be executed. T0IF will not be clear until firmware writes 0 to T0IF.

The block diagram of Timer0 and WDT is shown in the figure below.

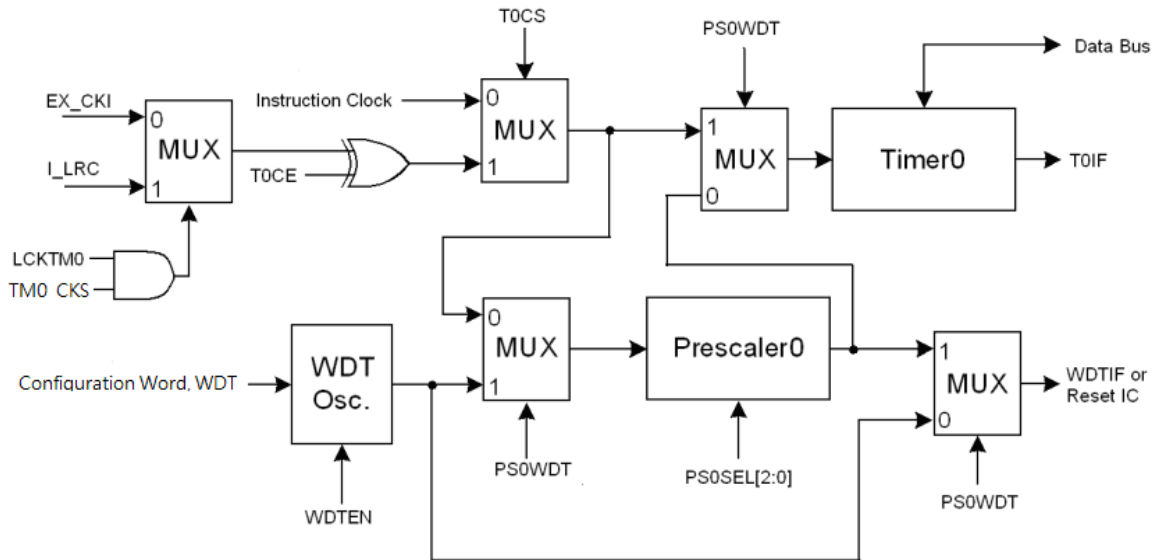


Figure 10 Block Diagram of Timer0 and WDT

3.8 Timer1/PWM1/Buzzer1

Timer1 is an 10-bit down-count timer with Prescaler1 whose dividing rate is programmable. The output of Timer1 can be used to generate PWM1 output and Buzzer1 output. Timer1 builds in auto-reload function and Timer1 reload register stores reload data with double buffers. When user write Timer1 reload register, write Timer1 MSB 2 bits(TMRH[5:4]) first and write TMR1 second, Timer1 reload register will be updated to Timer1 counter after Timer1 overflow occurs when T1EN=1. If T1EN=0, Timer1 reload register will be updated to Timer1 counter after write TMR1 immediately. A read to the Timer1 will show the content of the Timer1 current count value. The block diagram of Timer1 is shown in the figure below.

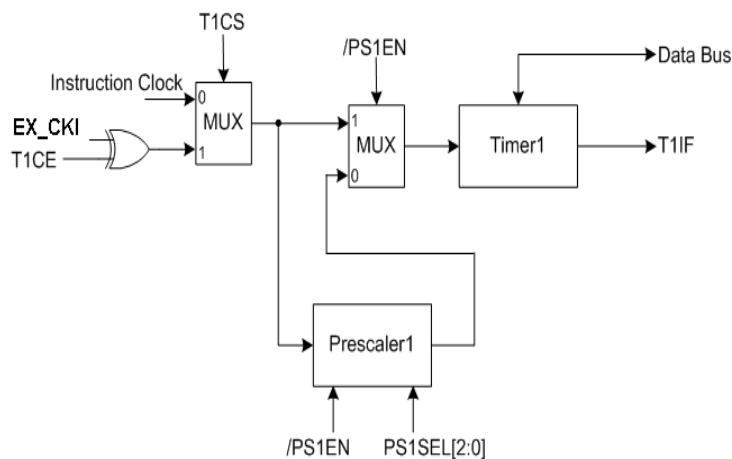


Figure 11 Block Diagram of Timer1

The operation of Timer1 can be enabled or disabled by register bit T1EN (T1CR1[0]). After Timer1 is enabled, its clock source can be instruction clock or pin EX_CK1 which is determined by register bit T1CS (T1CR2[5]). When T1CS is 1, EX_CK1 is selected as clock source. When T1CS is 0, instruction clock is selected as clock source. When EX_CK1 is selected, the active edge to decrease Timer1 is determined by register bit T1CE (T1CR2[4]). When T1CE is 1, high-to-low transition on EX_CK1 will decrease Timer1. When T1CE is 0, low-to-high transition on EX_CK1 will decrease Timer1. The selected clock source can be divided further by Prescaler1 before it is applied to Timer1. Prescaler1 is enabled by writing 0 to register bit /PS1EN (T1CR2[3]) and the dividing rate is from 1:2 to 1:256 determined by register bits PS1SEL[2:0] (T1CR2[2:0]). Current value of Prescaler1 can be obtained by reading register PS1CV.

Timer1 provide two kinds of operating mode: one is One-Shot mode and the other is Non-Stop mode. When register bit T1OS (T1CR1[2]) is 1, One-Shot mode is selected. Timer1 will count down once from initial value stored on register TMR1 to 0x00, i.e. underflow is occurred. When register bit T1OS (T1CR1[2]) is 0, Non-Stop mode is selected. When underflow is occurred, there are two selections to start next down-count which is determined by register bit T1RL (T1CR1[1]). When T1RL is 1, the initial value stored on register TMR1 will be restored and start next down-count from this initial value. When T1RL is 0, Timer1 will start next down-count from 0x3FF.

When Timer1 is underflow, the register bit T1IF (INTF[3]) will be set to 1 to indicate Timer1 underflow event is occurred. If register bit T1IE (INTE[3]) and GIE are both set to 1, interrupt request will occur and interrupt service routine will be executed. T1IF will not be clear until firmware writes 0 to T1IF.

The timing chart of Timer1 is shown in the following figure.

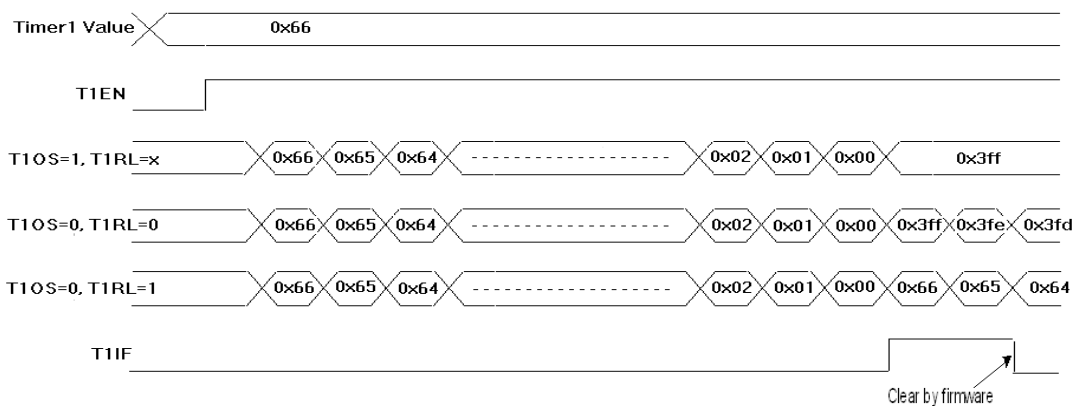


Figure 12 Timer1 Timing Chart

The PWM1 output can be available on I/O pin PB2 when register bit PWM1OEN (T1CR1[7]) is set to 1. Moreover, PB2 will become output pin automatically. The active state of PWM1 output is determined by register bit PWM1OAL (T1CR1[6]). When PWM1OAL is 1, PWM1 output is active low. When PWM1OAL is 0, PWM1

output is active high. Moreover, the duty cycle and frame rate of PWM1 are both programmable. The duty cycle is determined by registers TMRH[1:0] and PWM1DUTY[7:0]. When PWM1DUTY is 0, PWM1 output will be never active. When PWM1DUTY is 0x3FF, PWM1 output will be active for 1023 Timer1 input clocks. The frame rate is determined by TMRH[5:4] + TMR1[7:0] initial value. Therefore, PWM1DUTY value must be less than or equal to TMRH[5:4] + TMR1[7:0]. When user write PWM1DUTY, write PWM1DUTY[9:8] MSB 2 bits(TMRH[1:0]) first and write PWM1DUTY[7:0] second, PWM1 duty register will be updated after Timer1 overflow occurs. The block diagram of PWM1 is illustrated in the following figure.

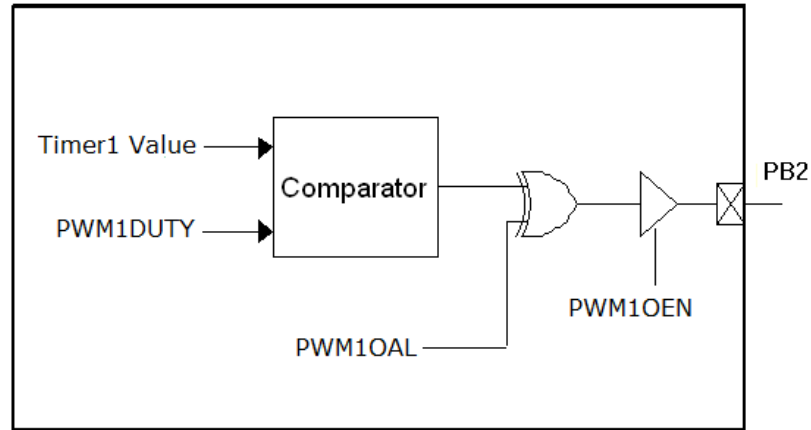


Figure 13 PWM1 Block Diagram

The Buzzer1 output (BZ1) can be available on I/O pin PB2, when register bit BZ1EN (BZ1CR1[7]) is set to 1 and corresponding configuration word PB.2 is BUZZER. When BZ1EN is set to 1, PB2 will become output pin automatically. The frequency of BZ1 can be derived from Timer1 output or Prescaler1 output and dividing rate is determined by register bits BZ1FSEL[3:0] (BZ1CR[3:0]). When BZ1FSEL[3] is 0, Prescaler1 output is selected to generate BZ1 output. When BZ1FSEL[3] is 1, Timer1 output is selected to generate BZ1 output. The dividing rate can be from 1:2 to 1:256 in order to generate all kinds of frequency. The block diagram of Buzzer1 is illustrated in the following figure.

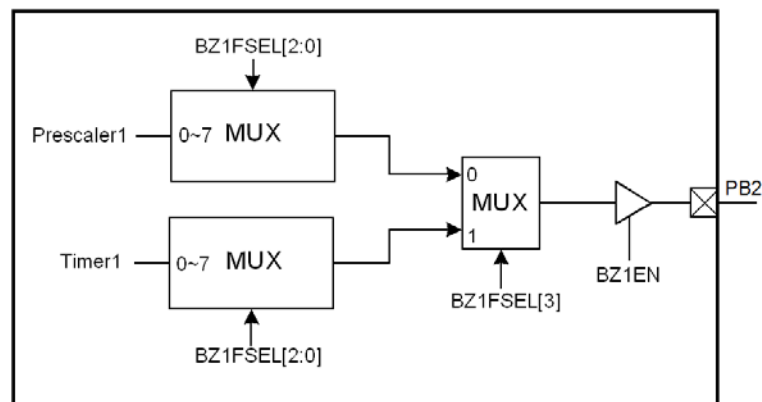


Figure 14 Buzzer1 Block Diagram

3.9 PWM2

The PWM2 output can be available on I/O pin PB0 when register bit PWM2OEN (P2CR[7]) is set to 1 . When PWM2OEN=1, PB0 will become output pin automatically. The active state of PWM2 output is determined by register bit PWM2OAL (P2CR[6]). When PWM2OAL is 1, PWM2 output is active low. When PWM2OAL is 0, PWM2 output is active high. Moreover, the duty cycle and frame rate of PWM2 are both programmable. The duty cycle is determined by register PWM2DUTY. When PWM2DUTY is 0, PWM2 output will be never active. When PWM2DUTY is 0x3FF, PWM2 output will be active for 1023 Timer1 input clocks. The frame rate is determined by TMRH[5:4],TMR1[7:0] initial value. Therefore, PWM2DUTY value must be less than or equal to TMR1[9:0]. When user write PWM2DUTY, write PWM2DUTY[9:8] MSB 2 bits(TMRH[3:2]) first and write PWM2DUTY[7:0] second, PWM2 duty register will be updated after Timer1 overflow occurs. The block diagram of PWM2 is illustrated in the following figure.

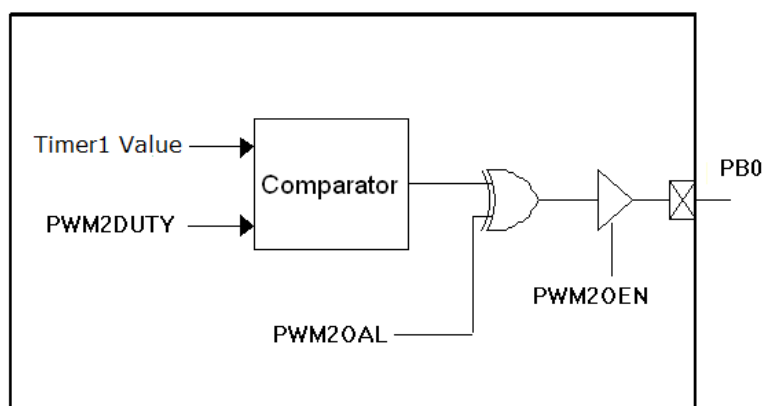


Figure 15 PWM2 Block Diagram

3.10 PWM3

The PWM3 output can be available on I/O pin PB3 when register bit PWM3OEN (P3CR[7]) is set to 1. When PWM3OEN=1, PB3 will become output pin automatically. The active state of PWM3 output is determined by register bit PWM3OAL (P3CR[6]). When PWM3OAL is 1, PWM3 output is active low. When PWM3OAL is 0, PWM3 output is active high. Moreover, the duty cycle and frame rate of PWM3 are both programmable. The duty cycle is determined by register PWM3DUTY. When PWM3DUTY is 0, PWM3 output will be never active. When PWM3DUTY is 0x3FF, PWM3 output will be active for 1023 Timer1 input clocks. The frame rate is determined by TMRH[5:4],TMR1[7:0] initial value. Therefore, PWM3DUTY value must be less than or equal to TMR1[9:0]. When user write PWM3DUTY, write PWM3DUTY[9:8] MSB 2 bits(PWM3RH[1:0]) first and write PWM3DUTY[7:0] second, PWM3 duty register will be updated after Timer1 overflow occurs. The block diagram of PWM3 is illustrated in the following figure.

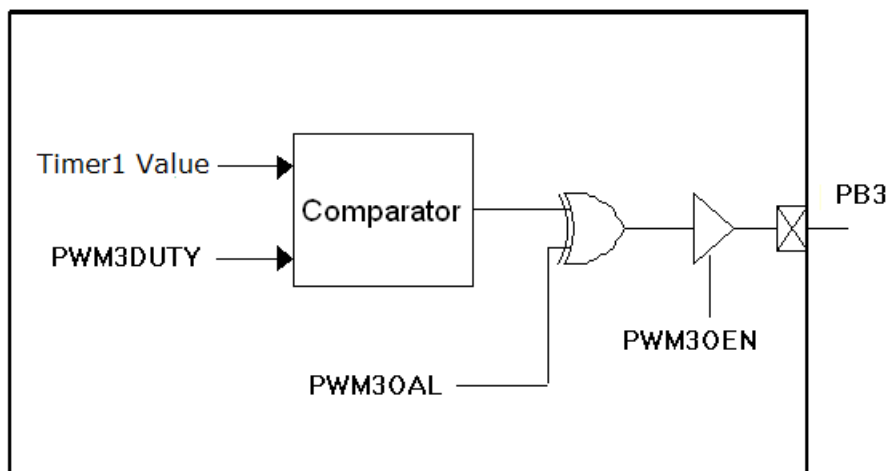


Figure 16 PWM3 Block Diagram

3.11 IR Carrier

The IR carrier will be generated after register bit IREN (IRCR[0]) is set to 1. Moreover, PB3 will become output pin automatically. When IREN is clear to 0, PB3 will become general I/O pin as it was configured.

The IR carrier frequency is selectable by register bit IRF57K (IRCR[1]). When IRF57K is 1, IR carrier frequency is 62.5KHz. When IRF57K is 0, IR carrier frequency is 41.6KHz.

The active state (polarity) of IR carrier is selectable according to PB3 output data. When register bit IRCSEL (IRCR[2]) is 1, IR carrier will be present on pin PB3 when its output data is 0. When register bit IRCSEL (IRCR[2]) is 0, IR carrier will be present on pin PB3 when its output data is 1. The polarity of IR carrier is shown in the following figure.

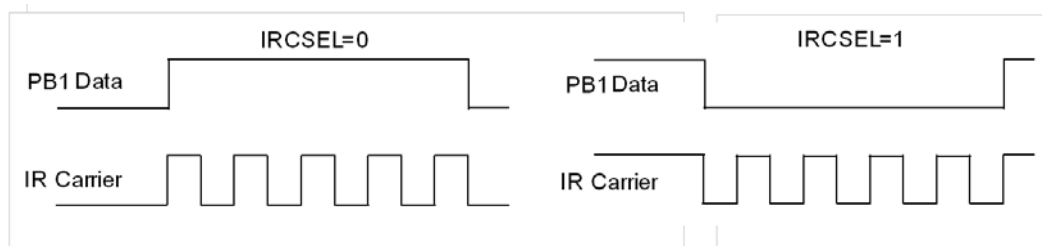


Figure 17 Polarity of IR Carrier vs. Output Data

3.12 Low Voltage Detector (LVD)

NY8TM52D low voltage detector (LVD) built-in precise band-gap reference for accurately detecting V_{DD} level. If $LVDEN(\text{register PCON}[5])=1$ and V_{DD} voltage value falls below LVD voltage which is selected by $LVDS[3:0]$ as table shown below, the LVD output will become low. If the LVD interrupt is enabled, the LVD interrupt flag will be high and if $GIE=1$ it will force the program to execute interrupt service routine. Moreover, LVD real-state output can be polled by register $PCON1[6]$. The following is LVD block diagram:

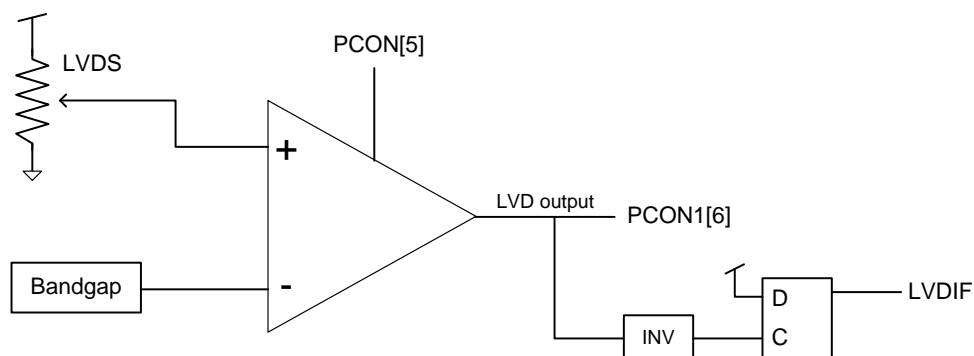


Figure 18 LVD block diagram

LVDS[3:0]	Voltage
0000	1.9V
0001	2.0V
0010	2.2V
0011	2.4V
0100	2.6V
0101	2.8V
0110	2.9V
0111	3.0V
1000	3.15V
1001	3.30V
1010	3.45V
1011	3.60V
1100	3.75V

LVDS[3:0]	Voltage
1101	3.90V
1110	4.05V
1111	4.15V

Table 12 LVD voltage select

Note:

1. The hysteresis voltage (from low to high) of LVD is about 0.1V.
2. In battery charging applications (detected voltage is from low to high), the LVD voltage select table should be as followed:

LVDS[3:0]	Voltage
0000	--
0001	--
0010	(2.2+0.1) V
0011	(2.4+0.1) V
0100	(2.6+0.1) V
0101	(2.8+0.1) V
0110	(2.9+0.1) V
0111	(3.0+0.1) V
1000	(3.15+0.1) V
1001	(3.30+0.1) V
1010	(3.45+0.1) V
1011	(3.60+0.1) V
1100	(3.75+0.1) V
1101	(3.90+0.1) V
1110	(4.05+0.1) V
1111	(4.15+0.1) V

The LVD control flow is as the following:

- Step1: Select LVD voltage by LVDS[3:0]
Step2: Set CMPCR = 0x0A
Step3: Set PCON[5]=1 (enable LVD)
Step4: Check LVD status by PCON1[6]

Note: If LVD voltage LVDS[3:0] is changed, user must wait at least 50us(@F_{Hosc}=1MHz) to get correct LVD status by PCON1[6]

3.13 Voltage Comparator

NY8TM52D provides voltage comparator and internal reference voltage with various analog comparing mode. The comparator non-inverting and inverting input can share with GPIO.

CMPEN (register PCON[2]) is used to enable and disable comparator. When CMPEN=0(default), comparator is disabled. When CMPEN=1, the comparator is enabled. In halt mode the comparator is disabled automatically.

The structure of comparator is shown in the following figure:

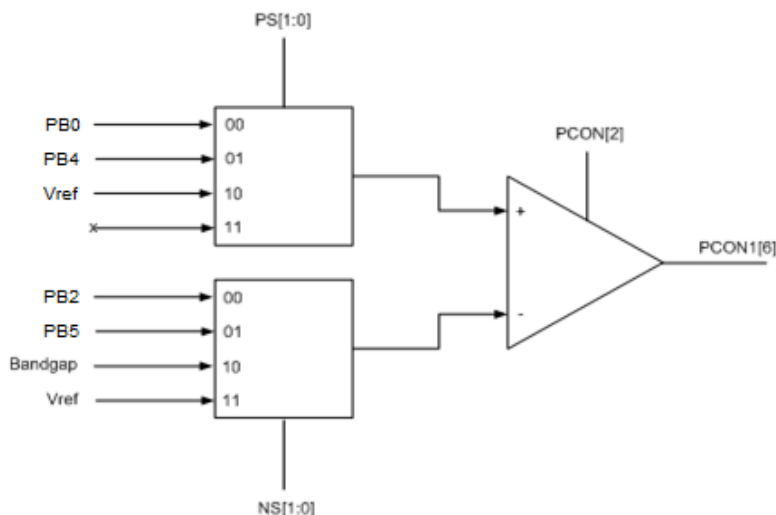


Figure 19 Comparator block diagram

3.13.1 Comparator Reference Voltage (Vref)

The internal reference voltage Vref is built by series resistance to provide different level of reference voltage.

RBIAS_H and RBIAS_L are used to select the maximum and minimum values of Vref, and LVDS[3:0] are used to select one of 16 voltage levels.

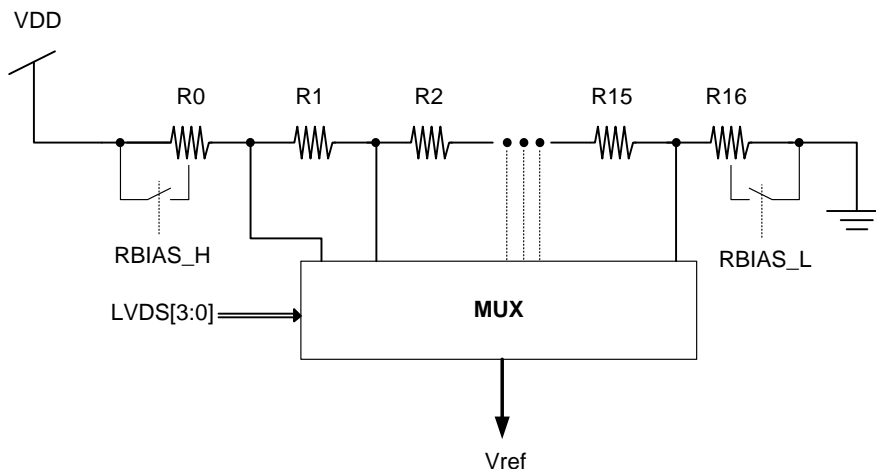


Figure 20 Vref hardware connection

The **Vref** is determined by RBIAS_H, RBIAS_L and LVDS[3:0]. The LVDS[3:0] is used to select one out of 16 reference voltages, the table shown below.

LVDS[3:0]	RBIAS_H=1 RBIAS_L=0	RBIAS_H=0 RBIAS_L=1
0000	65/128 V _{DD}	31/128 V _{DD}
0001	62/128 V _{DD}	29/128 V _{DD}
0010	56/128 V _{DD}	26/128 V _{DD}
0011	52/128 V _{DD}	23/128 V _{DD}
0100	48/128 V _{DD}	20/128 V _{DD}
0101	44/128 V _{DD}	18/128 V _{DD}
0110	43/128 V _{DD}	17/128 V _{DD}
0111	41/128 V _{DD}	16/128 V _{DD}
1000	39/128 V _{DD}	14/128 V _{DD}
1001	37/128 V _{DD}	13/128 V _{DD}
1010	35/128 V _{DD}	12/128 V _{DD}
1011	34/128 V _{DD}	11/128 V _{DD}
1100	32/128 V _{DD}	10/128 V _{DD}
1101	31/128 V _{DD}	9/128 V _{DD}
1110	30/128 V _{DD}	8/128 V _{DD}
1111	29/128 V _{DD}	7/128 V _{DD}

Table 13 The reference voltage Vref selection table

Note: The deviation of Vref is $\pm 0.1V$.

The non-inverting input of the comparator is determined by PS[1:0] (register CMPCR[3:2]).

The table is shown below

PS[1:0]	Non-inverting input
00	PB0
01	PB4
10	Vref
11	---

Table 14 Non-inverting input select

The inverting input of the comparator is determined by NS[1:0] (register CMPCR[1:0]).

The table is shown below

NS[1:0]	Inverting input
00	PB2
01	PB5
10	Bandgap (0.6V)
11	Vref

Table 15 Inverting input select

There are two ways to get the comparator output result: one is through register polling, the other is through probing output pad.

Comparator output can be polled by LVDOUT (register PCON1[6]).

To probe comparator output at output pad, set CMPOE (register OSCCR[6]) to 1, then PB3 will be the real-time state of the comparator output. It is noted that when CMPOE=1, the PWM3 function will be disabled if it is enabled.

3.14 Touch Pad

NY8TM52D can replace the mechanical switch or button with the touch pad function. A built-in LDO regulator for touch sensor can provide a stable capacitive sensing design for touch application.

Multiple Touch-Keys is from 1 touch key up to 4 touch keys decided by TPPADEN SFR. Scan which touch key chosen by TPCHS SFR. The modulation clock for touch key can be selected to be 1.31M, 1.12M, 1M, 0.88M or 0.75M. The touch key counter can be set by TPCNTH and TPCNTL before Touch-Pad take into operation. Then set TPRUN, the touch key will start to convert the touch sensing counter. Either touch external capacitor voltage beyond the comparator reference voltage or the touch counter overflow will terminate the modulation, also set TPCPIF=1 or TPOVIF=1 relative.

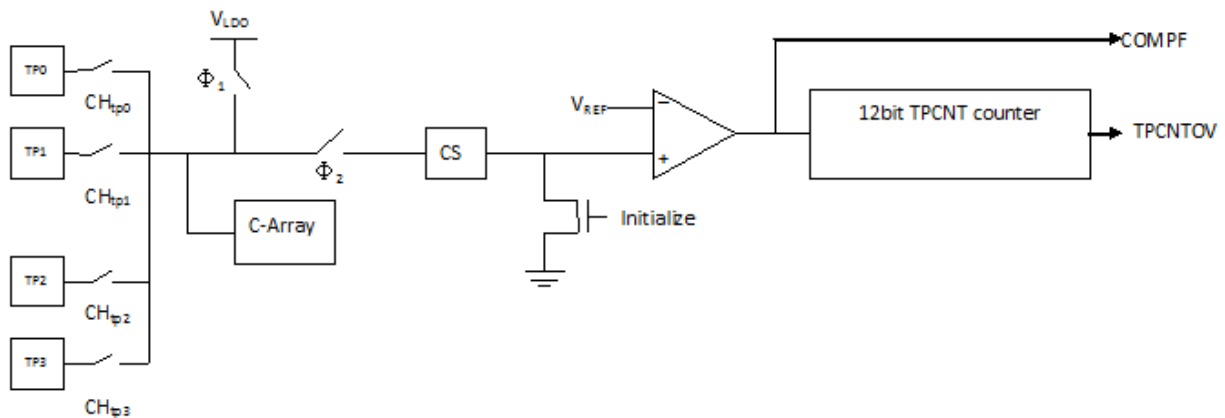
NY8TM52D support touch key slow mode to reduce the power consumption in CPU standby mode. The slow mode can be set 16Hz or 32Hz scan period. Then set TPRUN in TP slow mode, the modulation will start every 62ms or 31ms automatic.

Write the TPCHS SFR will reload the TPCNTH and TPCNTL to touch counter and set TPMD to TPCHSOFF.

Write the TPMD SFR will also reload the TPCNTH and TPCNTL to touch counter.

Clear the touch interrupt flag will reload TPCNTH and TPCNTL to touch counter.

In TPRUN mode, clear the touch interrupt flag will set TPMD to TPCHSOFF, but not in touch slow mode.



3.15 Watch-Dog Timer (WDT)

There is an on-chip free-running oscillator in NY8TM52D which is used by WDT. As this oscillator is independent of other oscillation circuits, WDT may still keep working during Standby mode and Halt mode.

WDT can be enabled or disabled by a configuration word. When WDT is enabled by configuration word, its operation still can be controlled by register bit WD TEN (PCON[7]) during program execution. Moreover, the mechanism after WDT time-out can reset NY8TM52D or issue an interrupt request which is determined by another configuration word. At the same time, register bit /TO (STATUS[4]) will be clear to 0 after WDT time-out.

The baseline of WDT time-out period can be 3.5 ms, 15 ms, 60 ms or 250 ms which is determined by two configuration words. The time-out period can be lengthened if Prescaler0 is assigned to WDT. Prescaler0 will be assigned to WDT by writing 1 to register bit PS0WDT. The dividing rate of Prescaler0 for WDT is determined by register bits PS0SEL[2:0] and depends on WDT time-out mechanism. The dividing rate is from 1:1 to 1:128 if WDT time-out will reset NY8TM52D and dividing rate is from 1:2 to 1:256 if WDT time-out will interrupt NY8TM52D.

When Prescaler0 is assigned to WDT, the execution of instruction CLRWDT will clear WDT, Prescaler0 and set /TO flag to 1.

If user selects interrupt for WDT time-out mechanism, register bit WDTIF (INTF[6]) will set to 1 after WDT is expired. It may generate an interrupt request if register bit WDTIE (INTE[6]) and GIE both set to 1. WDTIF will not be clear until firmware writes 0 to WDTIF.

3.16 Interrupt

NY8TM52D provide two kinds of interrupt: one is software interrupt and the other is hardware interrupt. Software interrupt is caused by execution of instruction INT. There are 8 hardware interrupts:

- Timer0 overflow interrupt.
- Timer1 underflow interrupt.
- WDT timeout interrupt.
- PB input change interrupt.
- External interrupt.
- LVD interrupt.
- Touch pad comparator interrupt..
- Touch pad counter overflow interrupt

GIE is global interrupt enable flag. It has to be 1 to enable hardware interrupt functions. GIE can be set by ENI instruction and clear to 0 by DISI instruction.

After instruction INT is executed, no matter GIE is set or clear, the next instruction will be fetched from address 0x001. At the same time, GIE will be clear to 0 by NY8TM52D automatically. This will prevent nested interrupt from happening. The last instruction of interrupt service routine of software interrupt has to be RETIE. Execution of this instruction will set GIE to 1 and return to original execution sequence.

While any of hardware interrupts is occurred, the corresponding bit of Interrupt Flag Register INTF will be set to 1. This bit will not be clear until firmware writes 0 to this bit. Therefore user can obtain information of which event causes hardware interrupt by polling register INTF. Note that only when the corresponding bit of Interrupt Enable register INTE is set to 1, will the corresponding interrupt flag be read. And if the corresponding bit of Interrupt Enable Register INTE is set to 1 and GIE is also 1, hardware interrupt will occur and next instruction will be fetched from 0x008. At the same time, the register bit GIE will be clear by NY8TM52D automatically. If user wants to implement nested interrupt, instruction ENI can be used as the first instruction of interrupt service routine which will set GIE to 1 again and allow other interrupt events to interrupt NY8TM52D again. Instruction RETIE has to be the last instruction of interrupt service routine which will set GIE to 1 and return to original execution sequence.

It should be noted that ENI instruction cannot be placed right before RETIE instruction because ENI instruction in interrupt service routine will trigger nested interrupt, but RETIE will clear internal interrupt processing after jump out of ISR, so it is possible for interrupt flag to be falsely cleared.

3.16.1 Timer0 Overflow Interrupt

Timer0 overflow (from 0x00 to 0xFF) will set register bit T0IF. This interrupt request will be serviced if T0IE and GIE are set to 1.

3.16.2 Timer1 Underflow Interrupt

Timer1 underflow (from 0x3FF to 0x00) will set register bit T1IF. This interrupt request will be serviced if T1IE and GIE are set to 1.

3.16.3 WDT Timeout Interrupt

When WDT is timeout and the configuration word selects WDT timeout will generate interrupt request, it will set register bit WDTIF. This interrupt request will be serviced if WDTIE and GIE are set to 1.

3.16.4 PB Input Change Interrupt

When PBx, $0 \leq x \leq 5$, is configured as input pin and corresponding register bit WUPBx is set to 1, a level change on these selected I/O pin(s) will set register bit PBIF. This interrupt request will be serviced if PBIE and GIE are set to 1. Note when PB0 is both set as level change interrupt and external interrupt, the external interrupt flag EIS will disable PB0 level change operation.

3.16.5 External Interrupt

According to the configuration of EIS=1 and INTEDG, the selected active edge on I/O pin PB0 will set register bit INTIF and this interrupt request will be served if INTIE and GIE are set to 1.

3.16.6 LVD Interrupt

When V_{DD} level falls below LVD voltage, LVD flag will go from high to low, and set the register bit LVDIF=1. This interrupt request will be serviced if LVDIE and GIE are set to 1.

3.16.7 Touch pad comparator interrupt

When touch external capacitor voltage is beyond touch comparator reference voltage, the TPCMP flag will go from low to high, and set the register bit TPCPIF. This interrupt request will be serviced if TPCPIE and GIE are set to 1.

3.16.8 Touch pad counter overflow interrupt

When touch counter overflow will set register bit TPOVIF. This interrupt request will be serviced if TPOVIE and GIE are set to 1.

3.17 Oscillation Configuration

Because NY8TM52D is a dual-clock IC, there are high oscillation (F_{HOSC}) and low oscillation (F_{LOSC}) which can be selected as system oscillation (F_{OSC}). The oscillators which could be used as F_{HOSC} are internal high RC oscillator (I_HRC). The oscillators which could be used as F_{LOSC} are internal low RC oscillator (I_LRC).

- (1) STPHOSC(OSCCR[1])=1 will stop F_{HOSC}
- (2) F_{HOSC} will be disabled automatically at Halt mode

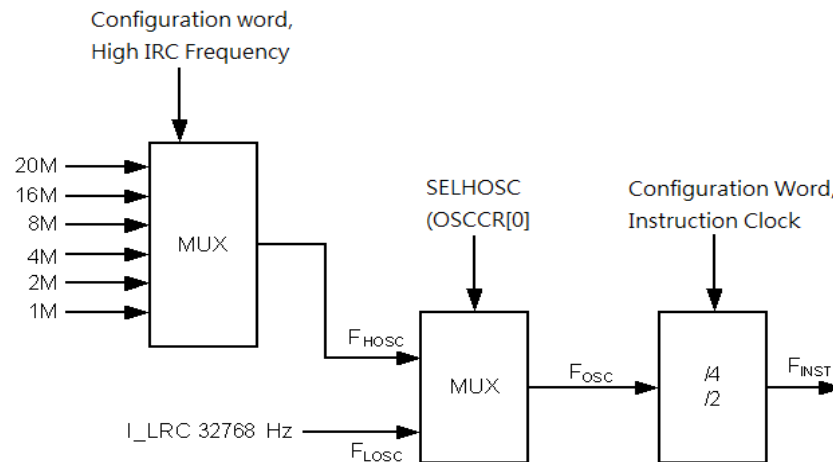


Figure 19 Oscillation Configuration of NY8TM52D

I_HRC output frequency is determined by three configuration words and it can be 1M, 2M, 4M, 8M, 16M or 20MHz.

When I_LRC is selected, its frequency is centered on 32768Hz.

Either F_{HOSC} or F_{LOSC} can be selected as system oscillation F_{OSC} according to the value of register bit SELHOSC (OSCCR[0]). When SELHOSC is 1, F_{HOSC} is selected as F_{OSC} . When SELHOSC is 0, F_{LOSC} is selected as F_{OSC} . Once F_{OSC} is determined, the instruction clock F_{INST} can be $F_{OSC}/2$ or $F_{OSC}/4$ according to value of a configuration word.

3.18 Operating Mode

NY8TM52D provides four kinds of operating mode to tailor all kinds of application and save power consumptions. These operating modes are Normal mode, Slow mode, Standby mode and Halt mode. Normal mode is designated for high-speed operating mode. Slow mode is designated for low-speed mode in order to save power consumption. At Standby mode, NY8TM52D will stop almost all operations except Timer0/Timer1/WDT/LVD in order to wake-up periodically. At Halt mode, NY8TM52D will sleep until external event or WDT trigger IC to wake-up.

The block diagram of four operating modes is described in the following figure.

Reset Event :
 - POR
 - BOR
 - LVR
 - RSTb pin enter low state
 - WDT timeout

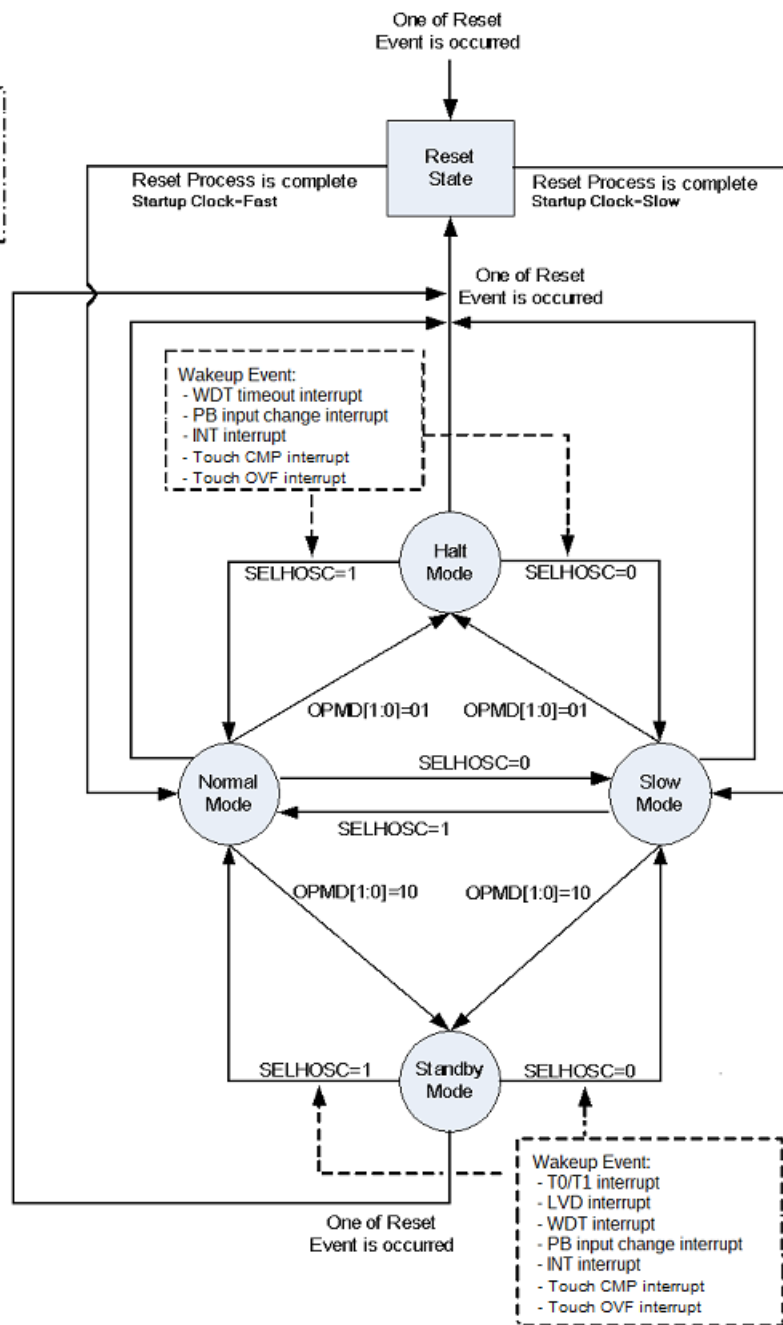


Figure 20 Four Operating Modes

3.18.1 Normal Mode

After any Reset Event is occurred and Reset Process is complete, NY8TM52D will begin to execute program under Normal mode or Slow mode. Which mode is selected after Reset Process is determined by the Startup Clock configuration word. If Startup Clock= I_HRC, NY8TM52D will enter Normal mode, if Startup Clock= I_LRC, NY8TM52D will enter Slow mode. At Normal mode, F_{HOSC} is selected as system oscillation in order to provide highest performance and its power consumption will be the largest among four operating modes. After power on or any reset trigger is released, NY8TM52D will enter Normal mode after reset process is complete.

- Instruction execution is based on F_{HOSC} and all peripheral modules may be active according to corresponding module enable bit.
- The F_{LOSC} is still active and running.
- IC can switch to Slow mode by writing 0 to register bit SELHOSC (OSCCR[0]).
- IC can switch to Standby mode or Halt mode by programming register bits OPMD[1:0] (OSCCR[3:2]).
- For real time clock applications, the NY8TM52D can run in normal mode, at the same time the low-frequency clock. Low Oscillator Frequency connects to timer0 clock. This is made possible by setting LCKTM0 to 1 and corresponding configuration word Timer0 source setting to 1.

3.18.2 Slow Mode

NY8TM52D will enter Slow mode by writing 0 to register bit SELHOSC. At Slow mode, F_{LOSC} is selected as system oscillation in order to save power consumption but still keep IC running. However, F_{HOSC} will not be disabled automatically by NY8TM52D. Therefore user can write 0 to register bit STPHOSC (OSCCR[1]) in slow mode to reduce power consumption further. But it is noted that it is forbidden to enter slow mode and stop F_{HOSC} at the same time, one must enter slow mode first, then disable F_{HOSC} , or the program may hang on.

- Instruction execution is based on F_{LOSC} and all peripheral modules may be active according to corresponding module enable bit.
- F_{HOSC} can be disabled by writing 1 to register bit STPHOSC.
- IC can switch to Standby mode or Halt mode by programming register bits OPMD[1:0].
- IC can switch to Normal mode by writing 1 to SELHOSC.

3.18.3 Standby Mode

NY8TM52D will enter Standby mode by writing 10b to register bits OPMD[1:0]. At Standby mode, however, F_{HOSC} will not be disabled automatically by NY8TM52D and user has to enter slow mode and write 1 to register bit STPHOSC in order to stop F_{HOSC} oscillation. Most of NY8TM52D peripheral modules are disabled but Timer can be still active if register bit T0EN/T1EN is set to 1. Therefore NY8TM52D can wake-up after Timer0/Timer1 is expired. The expiration period is determined by the register TMR0/TMR1, F_{INST} and other configurations for Timer0/Timer1.

- Instruction execution is stop and some peripheral modules may be active according to corresponding module enable bit.
- F_{HOSC} can be disabled by writing 1 to register bit STPHOSC.
- The F_{LOSC} is still active and running.
- IC can wake-up from Standby mode if any of (a) Timer0 overflow /Timer1 underflow interrupt, (b) WDT timeout interrupt, (c) PB input change interrupt, (d) INT external interrupt is happened or (e) LVD Interrupt.
- After wake-up from Standby mode, IC will return to Normal mode if SELHOSC=1, IC will return to Slow mode if SELHOSC=0.
- It is not recommended to change oscillator mode (normal to slow / slow to normal) and enter standby mode at the same time.

3.18.4 Halt Mode

NY8TM52D will enter Halt mode by executing instruction SLEEP or writing 01b to register bits OPMD[1:0]. After entering Halt mode, register bit /PD (STATUS[3]) will be clear to 0, register bit /TO (STATUS[4]) will be set to 1 and WDT will be clear but keep running.

At Halt mode, all of peripheral modules are disabled, instruction execution is stop and NY8TM52D can only wake-up by some specific events. Therefore, Halt mode is the most power saving mode provided by NY8TM52D.

- Instruction execution is stop and all peripheral modules are disabled.
- F_{HOSC} and F_{LOSC} are both disabled automatically.
- IC can wake-up from Halt mode if any of (a) WDT timeout interrupt, (b) PB input change interrupt or (c) INT or external interrupt is happened.
- After wake-up from Halt mode, IC will return to Normal mode if SELHOSC=1, IC will return to Slow mode if SELHOSC=0.

Note: You can change STPHOSC and enter Halt mode in the same instruction.

- It is not recommended to change oscillator mode (normal to slow / slow to normal) and enter standby mode at the same time

3.18.5 Wake-up Stable Time

The wake-up stable time of Halt mode is $16 \cdot F_{osc7}$. There is no need of wake-up stable time for Standby mode because either F_{HOSC} or F_{LOSC} is still running at Standby mode.

Before NY8TM52D enters Standby mode or Halt mode, user may execute instruction ENI. At this condition, NY8TM52D will branch to address 0x008 in order to execute interrupt service routine after wake-up. If instruction DISI is executed before entering Standby mode or Halt mode, the next instruction will be executed after wake-up.

3.18.6 Summary of Operating Mode

The summary of four operating modes is described in the following table.

Mode	Normal	Slow	Standby	Halt
F _{HOSC}	Enabled	STPHOSC	STPHOSC	Disabled
F _{LOSC}	Enabled	Enabled	Enabled	Disabled
Instruction Execution	Executing	Executing	Stop	Stop
Timer0/1	T0EN / T1EN	T0EN / T1EN	T0EN / T1EN	Disabled
WDT	Option and WDTEN	Option and WDTEN	Option and WDTEN	Option and WDTEN
Other Modules	Module enable bit	Module enable bit	Module enable bit	All disabled
Wake-up Source	-	-	<ul style="list-style-type: none"> - Timer0 overflow - Timer1 underflow - WDT timeout - PB input change - INTIE - LVD - Touch CMP INT - Touch OVF INT 	<ul style="list-style-type: none"> - WDT timeout - PB input change - INTIE - Touch CMP INT - Touch OVF INT

Table 12 Summary of Operating Modes

3.19 Reset Process

NY8TM52D will enter Reset State and start Reset Process when one of following Reset Event is occurred:

- Power-On Reset (POR) is occurred when V_{DD} rising is detected.
- Low-Voltage Reset (LVR) is occurred when operating V_{DD} is below pre-defined voltage.
- Pin RSTb is low state.
- WDT timeout reset.

Moreover, value of all registers will be initialized to their initial value or unchanged if its initial value is unknown. The status bits /TO and /PD could be initialized according to which event causes reset. The /TO and /PD value and its associated event is summarized in the table below.

Event	/TO	/PD
POR, LVR	1	1
RSTb reset from non-Halt mode	unchanged	unchanged
RSTb reset from Halt mode	1	1
WDT reset from non-Halt mode	0	1
WDT reset from Halt mode	0	0
SLEEP executed	1	0
CLRWDWT executed	1	1

Table 13 Summary of /TO & /PD Value and its Associated Event

After Reset Event is released, NY8TM52D will start Reset Process. It will wait certain amount of period for oscillation stable no matter what kind of oscillator is adopted. This period is called power-up reset time and is determined by three-bit configuration words which can be 140u, 4.5ms, 18ms, 72ms or 288ms. After oscillator is stable, NY8TM52D will wait further 16 clock cycles of F_{OSC} (oscillator start-up time, OST) and Reset Process is complete.

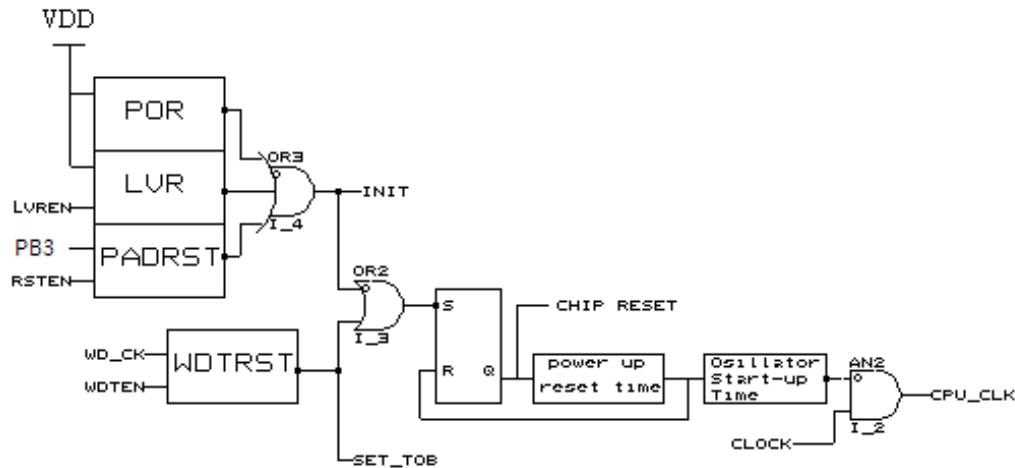


Figure 21 Block diagram of on-chip reset circuit

For slow V_{DD} power-up, it is recommended to use RSTb reset, as the following figure.

- It is recommended the R value should be not greater than 40kΩ.
- The R1 value=100Ω to 1kΩ will prevent high current, ESD or Electrical overstress flowing into reset pin.
- The diode helps discharge quickly when power down.

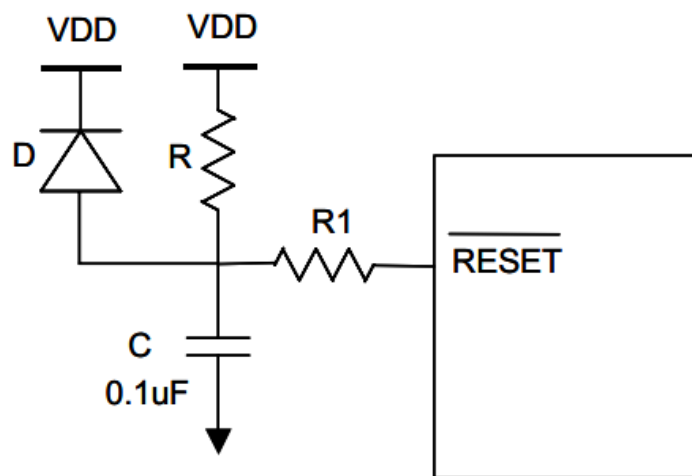


Figure 22 Block Diagram of Reset Application

4. Instruction Set

NY8TM52D provides 55 powerful instructions for all kinds of applications.

Inst.	OP		Operation	Cyc.	Flag
	1	2			
Arithmetic Instructions					
ANDAR	R	d	dest = ACC & R	1	Z
IORAR	R	d	dest = ACC R	1	Z
XORAR	R	d	dest = ACC ⊕ R	1	Z
ANDIA	i		ACC = ACC & i	1	Z
IORIA	i		ACC = ACC i	1	Z
XORIA	i		ACC = ACC ⊕ i	1	Z
RRR	R	d	Rotate right R	1	C
RLR	R	d	Rotate left R	1	C
BSR	R	bit	Set bit in R	1	-
BCR	R	bit	Clear bit in R	1	-
INCR	R	d	Increase R	1	Z
DECR	R	d	Decrease R	1	Z
COMR	R	d	dest = ~R	1	Z
Conditional Instructions					
BTRSC	R	bit	Test bit in R, skip if clear	1 or 2	-
BTRSS	R	bit	Test bit in R, skip if set	1 or 2	-
INCRSZ	R	d	Increase R, skip if 0	1 or 2	-
DECRSZ	R	d	Decrease R, skip if 0	1 or 2	-
Data Transfer Instructions					
MOVAR	R		Move ACC to R	1	-
MOVR	R	d	Move R	1	Z
MOVIA	i		Move immediate to ACC	1	-
SWAPR	R	d	Swap halves R	1	-
IOST	F		Load ACC to F-page SFR	1	-
IOSTR	F		Move F-page SFR to ACC	1	-
SFUN	S		Load ACC to S-page SFR	1	-
SFUNR	S		Move S-page SFR to ACC	1	-
T0MD			Load ACC to T0MD	1	-
T0MDR			Move T0MD to ACC	1	-
TABLEA			Read ROM	2	-

Inst.	OP		Operation	Cyc.	Flag
	1	2			
Arithmetic Instructions					
ADDAR	R	d	dest = R + ACC	1	Z, DC, C
SUBAR	R	d	dest = R + (~ACC)	1	Z, DC, C
ADCAR	R	d	dest = R + ACC + C	1	Z, DC, C
SBCAR	R	d	dest = R + (~ACC) + C	1	Z, DC, C
ADDIA	i		ACC = i + ACC	1	Z, DC, C
SUBIA	i		ACC = i + (~ACC)	1	Z, DC, C
ADCIA	i		ACC = i + ACC + C	1	Z, DC, C
SBCIA	i		ACC = i + (~ACC) + C	1	Z, DC, C
DAA			Decimal adjust for ACC	1	C
CMPAR	R		Compare R with ACC	1	Z, C
CLRA			Clear ACC	1	Z
CLRR			Clear R	1	Z
Data Transfer Instructions					
TFUN	T		Load ACC to T-page SFR	1	
TFUNR	T		Move T-page SFR to ACC	1	
Other Instructions					
NOP			No operation	1	-
SLEEP			Go into Halt mode	1	/TO, /PD
CLRWDT			Clear Watch-Dog Timer	1	/TO, /PD
ENI			Enable interrupt	1	-
DISI			Disable interrupt	1	-
INT			Software Interrupt	3	-
RET			Return from subroutine	2	-
RETIE			Return from interrupt and enable interrupt	2	-
RETIA	i		Return, place immediate in ACC	2	-
CALLA			Call subroutine by ACC	2	-
GOTOA			unconditional branch by ACC	2	-
LCALL	adr		Call subroutine	2	-
LGOTO	adr		unconditional branch	2	-

Table 14 Instruction Set

ACC: Accumulator.

adr: immediate address.

bit: bit address within an 8-bit register R.

C: Carry/Borrow bit

C=1, carry is occurred for addition instruction or borrow is **NOT** occurred for subtraction instruction.

C=0, carry is not occurred for addition instruction or borrow **IS** occurred for subtraction instruction.

d: Destination

If d is "0", the result is stored in the ACC.

If d is "1", the result is stored back in register R.

DC: Digital carry flag.

dest: Destination.

F: F-page SFR, F is 0x5 ~ 0xF.

i: 8-bit immediate data.

PC: Program Counter.

PCHBUF: High Byte Buffer of Program Counter.

/PD: Power down flag bit

/PD=1, after power-up or after instruction CLRWDW is executed.

/PD=0, after instruction SLEEP is executed.

Prescaler: Prescaler0 dividing rate.

R: R-page SFR, R is 0x00 ~ 0x3F.

S: S-page SFR, S is 0x0 ~ 0x13.

T: S-page SFR, T is 0x0 ~ 0x7F

T0MD: T0MD register.

TBHP: The high-Byte at target address in ROM.

TBHD: Store the high-Byte data at target address in ROM.

/TO: Time overflow flag bit

/TO=1, after power-up or after instruction CLRWDW or SLEEP is executed.

/TO=0, WDT timeout is occurred.

WDT: Watchdog Timer Counter.

Z: Zero flag.

ADCAR	Add ACC and R with Carry
Syntax:	ADCAR R, d
Operand:	$0 \leq R \leq 63$ $d = 0, 1.$
Operation:	$R + ACC + C \rightarrow \text{dest}$
Status affected:	Z, DC, C
Description:	Add the contents of ACC and register R with Carry. If d is 0, the result is stored in ACC. If d is 1, the result is stored back to R.
Cycle	1
Example:	ADCAR R, d before executing instruction: ACC=0x12, R=0x34, C=1, d=1. after executing instruction: R=0x47, ACC=0x12, C=0.

ADDAR	Add ACC and R
Syntax:	ADDAR R, d
Operand:	$0 \leq R \leq 63$ $d = 0, 1.$
Operation:	$ACC + R \rightarrow \text{dest}$
Status affected:	Z, DC, C
Description:	Add the contents of ACC and R. If d is 0, the result is stored in ACC. If d is 1, the result is stored back to R.
Cycle:	1
Example:	ADDAR R, d before executing instruction: ACC=0x12, R=0x34, C=1, d=1. after executing instruction: R=0x46, ACC=0x12, C=0.

ADCIA	Add ACC and Immediate with Carry
Syntax:	ADCIA i
Operand:	$0 \leq i < 255$
Operation:	$ACC + i + C \rightarrow ACC$
Status affected:	Z, DC, C
Description:	Add the contents of ACC and the 8-bit immediate data i with Carry. The result is placed in ACC.
Cycle:	1
Example:	ADCIA i before executing instruction: ACC=0x12, i=0x34, C=1. after executing instruction: ACC=0x47, C=0.

ADDIA	Add ACC and Immediate
Syntax:	ADDIA i
Operand:	$0 \leq i < 255$
Operation:	$ACC + i \rightarrow ACC$
Status affected:	Z, DC, C
Description:	Add the contents of ACC with the 8-bit immediate data i. The result is placed in ACC.
Cycle:	1
Example:	ADDIA i before executing instruction: ACC=0x12, i=0x34, C=1. after executing instruction: ACC=0x46, C=0.

ANDAR	AND ACC and R
Syntax:	ANDAR R, d
Operand:	$0 \leq R \leq 63$. $d = 0, 1$.
Operation:	$ACC \& R \rightarrow dest$
Status affected:	Z
Description:	The content of ACC is AND'ed with R. If d is 0, the result is stored in ACC. If d is 1, the result is stored back to R.
Cycle:	1
Example:	ANDAR R, d before executing instruction: ACC=0x5A, R=0xAF, d=1. after executing instruction: R=0x0A, ACC=0x5A, Z=0.

BCR	Clear Bit in R
Syntax:	BCR R, bit
Operand:	$0 \leq R \leq 63$ $0 \leq bit \leq 7$
Operation:	$0 \rightarrow R[bit]$
Status affected:	--
Description:	Clear the bit th position in R.
Cycle:	1
Example:	BCR R,B2 before executing instruction: R=0x5A, B2=0x3. after executing instruction: R=0x52.

ANDIA	AND Immediate with ACC
Syntax:	ANDIA i
Operand:	$0 \leq i < 255$
Operation:	$ACC \& i \rightarrow ACC$
Status affected:	Z
Description:	The content of ACC register is AND'ed with the 8-bit immediate data i. The result is placed in ACC.
Cycle:	1
Example:	ANDIA i before executing instruction: ACC=0x5A, i=0xAF. after executing instruction: ACC=0x0A, Z=0.

BSR	Set Bit in R
Syntax:	BSR R, bit
Operand:	$0 \leq R \leq 63$ $0 \leq bit \leq 7$
Operation:	$1 \rightarrow R[bit]$
Status affected:	--
Description:	Set the bit th position in R.
Cycle:	1
Example:	BSR R,B2 before executing instruction: R=0x5A, B2=0x2. after executing instruction: R=0x5E.

BTRSC Test Bit in R and Skip if Clear

Syntax:	BTRSC R, bit
Operand:	$0 \leq R \leq 63$ $0 \leq \text{bit} \leq 7$
Operation:	Skip next instruction, if R[bit] = 0.
Status affected:	--
Description:	If R[bit] = 0, the next instruction which is already fetched is discarded and a NOP is executed instead. Therefore it makes this instruction a two-cycle instruction.
Cycle:	1 or 2(skip)
Example:	BTRSC R, B2 Instruction1 Instruction2 before executing instruction: R=0x5A, B2=0x2. after executing instruction: because R[B2]=0, instruction1 will not be executed, the program will start execute instruction from instruction2.

BTRSS Test Bit in R and Skip if Set

Syntax:	BTRSS R, bit
Operand:	$0 \leq R \leq 63$ $0 \leq \text{bit} \leq 7$
Operation:	Skip next instruction, if R[bit] = 1.
Status affected:	--
Description:	If R[bit] = 1, the next instruction which is already fetched is discarded and a NOP is executed instead. Therefore it makes this instruction a two-cycle instruction.
Cycle:	1 or 2(skip)
Example:	BTRSS R, B2 Instruction2 Instruction3 before executing instruction: R=0x5A, B2=0x3. after executing instruction: because R[B2]=1, instruction2 will not be executed, the program will start execute instruction from instruction3.

CALLA Call Subroutine

Syntax:	CALLA
Operand:	--
Operation:	PC + 1 \rightarrow Top of Stack {TBHP, ACC} \rightarrow PC
Status affected:	--
Description:	The return address (PC + 1) is pushed onto top of Stack. The contents of TBHP[2:0] is loaded into PC[10:8] and ACC is loaded into PC[7:0].
Cycle:	2
Example:	CALLA before executing instruction: TBHP=0x02, ACC=0x34. PC=A0. Stack pointer=1. after executing instruction: PC=0x234, Stack[1]=A0+1, Stack pointer=2.

CLRA Clear ACC

Syntax:	CLRA
Operand:	--
Operation:	00h \rightarrow ACC 1 \rightarrow Z
Status affected:	Z
Description:	ACC is clear and Z is set to 1.
Cycle:	1
Example:	CLRA before executing instruction: ACC=0x55, Z=0. after executing instruction: ACC=0x00, Z=1.

CLRR	Clear R
Syntax:	CLRR R
Operand:	$0 \leq R \leq 63$
Operation:	$00h \rightarrow R$ $1 \rightarrow Z$
Status affected:	Z
Description:	The content of R is clear and Z is set to 1.
Cycle:	1
Example:	CLRR R before executing instruction: R=0x55, Z=0. after executing instruction: R=0x00, Z=1.

COMR	Complement R
Syntax:	COMR R, d
Operand:	$0 \leq R \leq 63$ $d = 0, 1.$
Operation:	$\sim R \rightarrow \text{dest}$
Status affected:	Z
Description:	The content of R is complemented. If d is 0, the result is stored in ACC. If d is 1, the result is stored back to R.
Cycle:	1
Example:	COMR, d before executing instruction: R=0xA6, d=1, Z=0. after executing instruction: R=0x59, Z=0.

CLRWDT	Clear Watch-Dog Timer
Syntax:	CLRWDT
Operand:	--
Operation:	$00h \rightarrow \text{WDT},$ $00h \rightarrow \text{WDT prescaler}$ $1 \rightarrow /TO$ $1 \rightarrow /PD$
Status affected:	/TO, /PD
Description:	Executing CLRWDT will reset WDT, Prescaler0 if it is assigned to WDT. Moreover, status bits /TO and /PD will be set to 1.
Cycle:	1
Example:	CLRWDT before executing instruction: /TO=0 after executing instruction: /TO=1

CMPAR	Compare ACC and R
Syntax:	CMPAR R
Operand:	$0 \leq R \leq 63$
Operation:	$R - \text{ACC} \rightarrow (\text{No restore})$
Status affected:	Z, C
Description:	Compare ACC and R by subtracting ACC from R with 2's complement representation. The content of ACC and R is not changed.
Cycle:	1
Example:	CMPAR R before executing instruction: R=0x34, ACC=12, Z=0, C=0. after executing instruction: R=0x34, ACC=12, Z=0, C=1.

DAA Convert ACC Data Format from Hexadecimal to Decimal

Syntax: DAA

Operand: --

Operation: $\text{ACC(hex)} \rightarrow \text{ACC(dec)}$

Status affected: C

Description: Convert ACC data format from hexadecimal format to decimal format after addition operation and restore result to ACC. DAA instruction must be placed after addition operation if decimal format is required.

Cycle: 1

Example: ADDAR R,d
DAA
before executing instruction:
ACC=0x28, R=0x25, d=0.
after executing instruction:
ACC=0x53, C=0.

DECRSZ Decrease R, Skip if 0

Syntax: DECRSZ R, d

Operand: $0 \leq R \leq 63$
d = 0, 1.

Operation: $R - 1 \rightarrow \text{dest}$,
Skip if result = 0

Status affected: --

Description: Decrease R first. If d is 0, the result is stored in ACC. If d is 1, the result is stored back to R.
If result is 0, the next instruction which is already fetched is discarded and a NOP is executed instead. Therefore it makes this instruction a two-cycle instruction.

Cycle: 1 or 2(skip)

Example: DECRSZ R, d
instruction2
instruction3
before executing instruction:
R=0x1, d=1, Z=0.
after executing instruction:
R=0x0, Z=1, and instruction will skip instruction2 execution because the operation result is zero.

DECR Decrease R

Syntax: DECR R, d

Operand: $0 \leq R \leq 63$
d = 0, 1.

Operation: $R - 1 \rightarrow \text{dest}$

Status affected: Z

Description: Decrease R. If d is 0, the result is stored in ACC. If d is 1, the result is stored back to R.

Cycle: 1

Example: DECR R, d
before executing instruction:
R=0x01, d=1, Z=0.
after executing instruction:
R=0x00, Z=1.

DISI Disable Interrupt Globally

Syntax: DISI

Operand: --

Operation: Disable Interrupt, $0 \rightarrow \text{GIE}$

Status affected: --

Description: GIE is clear to 0 in order to disable all interrupt requests.

Cycle: 1

Example: DISI
before executing instruction:
GIE=1.
After executing instruction:
GIE=0.

ENI	Enable Interrupt Globally	INCR	Increase R
Syntax:	ENI	Syntax:	INCR R, d
Operand:	--	Operand:	$0 \leq R \leq 63$ $d = 0, 1.$
Operation:	Enable Interrupt, $1 \rightarrow \text{GIE}$	Operation:	$R + 1 \rightarrow \text{dest.}$
Status affected:	--	Status affected:	Z
Description:	GIE is set to 1 in order to enable all interrupt requests.	Description:	Increase R. If d is 0, the result is stored in ACC. If d is 1, the result is stored back to R.
Cycle:	1	Cycle:	1
Example:	ENI before executing instruction: GIE=0. After executing instruction: GIE=1.	Example:	INCR R, d before executing instruction: R=0xFF, d=1, Z=0. after executing instruction: R=0x00, Z=1.

GOTOA	Unconditional Branch	INCRSZ	Increase R, Skip if 0
Syntax:	GOTOA	Syntax:	INCRSZ R, d
Operand:	--	Operand:	$0 \leq R \leq 63$ $d = 0, 1.$
Operation:	{TBHP, ACC} \rightarrow PC	Operation:	$R + 1 \rightarrow \text{dest.}$ Skip if result = 0
Status affected:	--	Status affected:	--
Description:	GOTOA is an unconditional branch instruction. The content of TBHP[2:0] is loaded into PC[10:8] and ACC is loaded into PC[7:0].	Description:	Increase R first. If d is 0, the result is stored in ACC. If d is 1, the result is stored back to R. If result is 0, the next instruction which is already fetched is discarded and a NOP is executed instead. Therefore it makes this instruction a two-cycle instruction.
Cycle:	2	Cycle:	1 or 2(skip)
Example:	GOTOA before executing instruction: PC=A0. TBHP=0x02, ACC=0x34. after executing instruction: PC=0x234.	Example:	INCRSZ R, d instruction2, instruction3. before executing instruction: R=0xFF, d=1, Z=0.

INCRSZ Increase R, Skip if 0

Syntax: INCRSZ R, d

after executing instruction:
 R=0x00, Z=1. And the program
 will skip instruction2 execution
 because the operation result is
 zero.

INT Software Interrupt

Syntax: INT

Operand: --

Operation: PC + 1 → Top of Stack,
 001h → PC

Status affected: --

Description: Software interrupt. First, return
 address (PC + 1) is pushed onto
 the Stack. The address 0x001 is
 loaded into PC[10:0].

Cycle: 3

Example: INT
 before executing instruction:
 PC=address of INT code.
 after executing instruction:
 PC=0x01.

IORIA OR Immediate with ACC

Syntax: IORIA i

Operand: $0 \leq i < 255$

Operation: ACC | i → ACC

Status affected: Z

Description: OR ACC with 8-bit immediate data
 i. The result is stored in ACC.

Cycle: 1

Example: IORIA i
 before executing instruction:
 i=0x50, ACC=0xAA, Z=0.
 after executing instruction:
 ACC=0xFA, Z=0.

IORAR OR ACC with R

Syntax: IORAR R, d

Operand: $0 \leq R \leq 63$
 d = 0, 1.

Operation: ACC | R → dest

Status affected: Z

Description: OR ACC with R. If d is 0, the result
 is stored in ACC. If d is 1, the result
 is stored back to R.

Cycle: 1

Example: IORAR R, d
 before executing instruction:
 R=0x50, ACC=0xAA, d=1, Z=0.
 after executing instruction:
 R=0xFA, ACC=0xAA, Z=0.

IOST Load F-page SFR from ACC

Syntax: IOST F

Operand: $0 \leq F \leq 15$

Operation: ACC → F-page SFR

Status affected: --

Description: F-page SFR F is loaded by content
 of ACC.

Cycle: 1

Example: IOST F
 before executing instruction:
 F=0x55, ACC=0xAA.
 after executing instruction:
 F=0xAA, ACC=0xAA.

IOSTR Move F-page SFR to ACC

Syntax: IOSTR F

Operand: $0 \leq F \leq 15$

Operation: F-page SFR \rightarrow ACC

Status affected: --

Description: Move F-page SFR F to ACC.

Cycle: 1

Example: IOSTR F
before executing instruction:
F=0x55, ACC=0xAA.
after executing instruction:
F=0x55, ACC=0x55.

LGOTO Unconditional Branch

Syntax: LGOTO adr

Operand: $0 \leq \text{adr} \leq 2047$

Operation: $\text{adr} \rightarrow \text{PC}[10:0]$.

Status affected: --

Description: LGOTO is an unconditional branch instruction. The 10-bit immediate address adr is loaded into PC[10:0].

Cycle: 2

Example: LGOTO Level
before executing instruction:
PC=A0.
after executing instruction:
PC=address of Level.

LCALL Call Subroutine

Syntax: LCALL adr

Operand: $0 \leq \text{adr} \leq 2047$

Operation: $\text{PC} + 1 \rightarrow \text{Top of Stack}$,
 $\text{adr} \rightarrow \text{PC}[10:0]$

Status affected: --

Description: The return address (PC + 1) is pushed onto top of Stack. The 10-bit immediate address adr is loaded into PC[10:0].

Cycle: 2

Example: LCALL SUB
before executing instruction:
PC=A0. Stack level=1
after executing instruction:
PC=address of SUB, Stack[1]=
A0+1, Stack pointer =2.

MOVAR Move ACC to R

Syntax: MOVAR R

Operand: $0 \leq R \leq 63$

Operation: $\text{ACC} \rightarrow R$

Status affected: --

Description: Move content of ACC to R.

Cycle: 1

Example: MOVAR R
before executing instruction:
R=0x55, ACC=0xAA.
after executing instruction:
R=0xAA, ACC=0xAA.

MOVR
Move to ACC or R

R=0x0, ACC=0x00, Z=1.

MOVIA
Move Immediate to ACC

Syntax:	MOVIA i
Operand:	$0 \leq i < 255$
Operation:	$i \rightarrow \text{ACC}$
Status affected:	--
Description:	The content of ACC is loaded with 8-bit immediate data i.
Cycle:	1
Example:	MOVIA i before executing instruction: i=0x55, ACC=0xAA. after executing instruction: ACC=0x55.

NOP
No Operation

Syntax:	NOP
Operand:	--
Operation:	No operation.
Status affected:	--
Description:	No operation.
Cycle:	1
Example:	NOP before executing instruction: PC=A0 after executing instruction: PC=A0+1

MOVR
Move to ACC or R

Syntax:	MOVR R, d
Operand:	$0 \leq R \leq 63$ d = 0, 1.
Operation:	$R \rightarrow \text{dest}$
Status affected:	Z
Description:	The content of R is move to destination. If d is 0, destination is ACC. If d is 1, destination is R and it can be used to check whether R is zero according to status flag Z after execution.
Cycle:	1
Example:	MOVR R, d before executing instruction: R=0x0, ACC=0xAA, Z=0, d=0. after executing instruction:

RETIE
Return from Interrupt and Enable Interrupt Globally

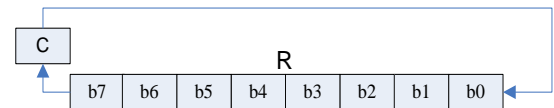
Syntax:	RETIE
Operand:	--
Operation:	Top of Stack \rightarrow PC 1 \rightarrow GIE
Status affected:	--
Description:	The PC is loaded from top of Stack as return address and GIE is set to 1.
Cycle:	2
Example:	RETIE before executing instruction: GIE=0, Stack level=2. after executing instruction: GIE=1, PC=Stack[2], Stack level

RETIE	Return from Interrupt and Enable Interrupt Globally
	=1.

RET	Return from Subroutine
	Stack level=2. after executing instruction: PC=Stack[2], Stack level=1.

RETIA	Return with Data in ACC
Syntax:	RETIA i
Operand:	$0 \leq i < 255$
Operation:	$i \rightarrow \text{ACC}$, Top of Stack $\rightarrow \text{PC}$
Status affected:	--
Description:	ACC is loaded with 8-bit immediate data i and PC is loaded from top of Stack as return address and GIE is set to 1.
Cycle:	2
Example:	RETIA i before executing instruction: GIE=0, Stack pointer =2, i=0x55, ACC=0xAA. after executing instruction: GIE=1, PC=Stack[2], Stack pointer =1, ACC=0x55.

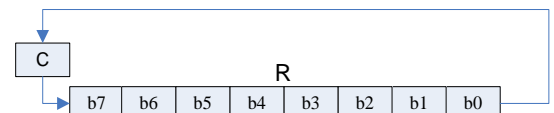
RLR	Rotate Left R Through Carry
Syntax:	RLR R, d
Operand:	$0 \leq R \leq 63$ $d = 0, 1$.
Operation:	$C \rightarrow \text{dest}[0]$, $R[7] \rightarrow C$, $R[6:0] \rightarrow \text{dest}[7:1]$



Status affected:	C
Description:	The content of R is rotated one bit to the left through flag Carry. If d is 0, the result is placed in ACC. If d is 1, the result is stored back to R.
Cycle:	1
Example:	RLR R, d before executing instruction: R=0xA5, d=1, C=0. after executing instruction: R=0x4A, C=1.

RET	Return from Subroutine
Syntax:	RET
Operand:	--
Operation:	Top of Stack $\rightarrow \text{PC}$
Status affected:	--
Description:	PC is loaded from top of Stack as return address.
Cycle:	2
Example:	RET before executing instruction:

RRR	Rotate Right R Through Carry
Syntax:	RRR R, d
Operand:	$0 \leq R \leq 63$ $d = 0, 1$.
Operation:	$C \rightarrow \text{dest}[7]$, $R[7:1] \rightarrow \text{dest}[6:0]$, $R[0] \rightarrow C$



RLR	Rotate Left R Through Carry
------------	------------------------------------

Syntax: RLR R, d

Status affected: C

Description: The content of R is rotated one bit to the right through flag Carry. If d is 0, the result is placed in ACC. If d is 1, the result is stored back to R.

Cycle: 1

Example: RRR R, d
before executing instruction:
R=0xA5, d=1, C=0.
after executing instruction:
R=0x52, C=1.

SBCAR	Subtract ACC and Carry from R
--------------	--------------------------------------

Syntax: SBCAR R, d

SBCAR	Subtract ACC and Carry from R
--------------	--------------------------------------

Syntax: SBCAR R, d

Operand: $0 \leq R \leq 63$
d = 0, 1.

Operation: $R + (\sim \text{ACC}) + C \rightarrow \text{dest}$

Status affected: Z, DC, C

Description: Subtract ACC and Carry from R with 2's complement representation. If d is 0, the result is placed in ACC. If d is 1, the result is stored back to R.

Cycle: 1

Example: SBCAR R, d
(a) before executing instruction:
R=0x05, ACC=0x06, d=1, C=0.
after executing instruction:
R=0xFE, C=0. (-2)
(b) before executing instruction:
R=0x05, ACC=0x06, d=1, C=1.
after executing instruction:
R=0xFF, C=0. (-1)
(c) before executing instruction:
R=0x06, ACC=0x05, d=1, C=0.
after executing instruction:
R=0x00, C=1. (-0), Z=1.
(d) before executing instruction:
R=0x06, ACC=0x05, d=1, C=1.
after executing instruction:
R=0x1, C=1. (+1)

SBCIA	Subtract ACC and Carry from Immediate
--------------	--

Syntax: SBCIA i

Operand: $0 \leq i < 255$

Operation: $i + (\sim \text{ACC}) + C \rightarrow \text{dest}$

Status affected: Z, DC, C

Description: Subtract ACC and Carry from 8-bit immediate data i with 2's complement representation. The result is placed in ACC.

Cycle: 1

Example: SBCIA i
(a) before executing instruction:
i=0x05, ACC=0x06, C=0.
after executing instruction:
ACC=0xFE, C=0. (-2)
(b) before executing instruction:
i=0x05, ACC=0x06, C=1.
after executing instruction:
ACC=0xFF, C=0. (-1)
(c) before executing instruction:
i=0x06, ACC=0x05, C=0.
after executing instruction:
ACC=0x00, C=1. (-0), Z=1.
(d) before executing instruction:
i=0x06, ACC=0x05, C=1.
after executing instruction:
ACC=0x1, C=1. (+1)

SFUNR Move S-page SFR from ACC

Description: Move S-page SFR S to ACC.
Cycle: 1
Example: SFUNR S
before executing instruction:
S=0x55, ACC=0xAA.
after executing instruction:
S=0x55, ACC=0x55.

SFUN Load S-page SFR from ACC

Syntax: SFUN S
Operand: $0 \leq S \leq 15$
Operation: ACC \rightarrow S-page SFR
Status affected: --
Description: S-page SFR S is loaded by content of ACC.
Cycle: 1
Example: SFUN S
before executing instruction:
S=0x55, ACC=0xAA.
after executing instruction:
S=0xAA, ACC=0xAA.

SLEEP Enter Halt Mode

Syntax: SLEEP
Operand: --
Operation: 00h \rightarrow WDT,
00h \rightarrow WDT prescaler
1 \rightarrow /TO
0 \rightarrow /PD
Status affected: /TO, /PD
Description: WDT and Prescaler0 are clear to 0.
/TO is set to 1 and /PD is clear to 0.
IC enter Halt mode.
Cycle: 1
Example: SLEEP
before executing instruction:
/PD=1, /TO=0.
after executing instruction:
/PD=0, /TO=1.

SFUNR Move S-page SFR from ACC

Syntax: SFUNR S
Operand: $0 \leq S \leq 15$
Operation: S-page SFR \rightarrow ACC
Status affected: --

SUBAR Subtract ACC from R

Syntax: SUBAR R, d

SUBAR	Subtract ACC from R
Operand:	$0 \leq R \leq 63$ $d = 0, 1.$
Operation:	$R - ACC \rightarrow \text{dest}$
Status affected:	Z, DC, C
Description:	Subtract ACC from R with 2's complement representation. If d is 0, the result is placed in ACC. If d is 1, the result is stored back to R.
Cycle:	1
Example:	SBCAR R, d (a) before executing instruction: R=0x05, ACC=0x06, d=1. after executing instruction: R=0xFF, C=0. (-1) (b) before executing instruction: R=0x06, ACC=0x05, d=1. after executing instruction: R=0x01, C=1. (+1)

SUBIA	Subtract ACC from Immediate
Syntax:	SUBIA i
Operand:	$0 \leq i < 255$
Operation:	$i - ACC \rightarrow ACC$
Status affected:	Z, DC, C
Description:	Subtract ACC from 8-bit immediate data i with 2's complement representation. The result is placed in ACC.
Cycle:	1
Example:	SUBIA i (a) before executing instruction: i=0x05, ACC=0x06. after executing instruction: ACC=0xFF, C=0. (-1) (b) before executing instruction: i=0x06, ACC=0x05, d=1. after executing instruction: ACC=0x01, C=1. (+1)

SWAPR	Swap High/Low Nibble in R
Syntax:	SWAPR R, d
Operand:	$0 \leq R \leq 63$ $d = 0, 1.$
Operation:	$R[3:0] \rightarrow \text{dest}[7:4].$ $R[7:4] \rightarrow \text{dest}[3:0]$
Status affected:	--
Description:	The high nibble and low nibble of R is exchanged. If d is 0, the result is placed in ACC. If d is 1, the result is stored back to R.
Cycle:	1
Example:	SWAPR R, d before executing instruction: R=0xA5, d=1. after executing instruction: R=0x5A.

TABLEA	Read ROM data
Syntax:	TABLEA
Operand:	--
Operation:	ROM data{ TBHP, ACC } [7:0] \rightarrow ACC ROM data{TBHP, ACC} [13:8] \rightarrow TBHD.
Status affected:	--
Description:	The 8 least significant bits of ROM pointed by {TBHP[2:0], ACC} is placed to ACC. The 6 most significant bits of ROM pointed by {TBHP[2:0], ACC} is placed to TBHD[5:0].
Cycle:	2
Example:	TABLEA before executing instruction: TBHP=0x02, CC=0x34. TBHD=0x01. ROM data[0x234]= 0x35AA after executing instruction: TBHD=0x35, ACC=0xAA.

SWAPR	Swap High/Low Nibble in R
--------------	----------------------------------

T0MD Load ACC to T0MD

Syntax:	T0MD
Operand:	--
Operation:	ACC \rightarrow T0MD
Status affected:	--
Description:	The content of T0MD is loaded by ACC.
Cycle:	1
Example:	T0MD before executing instruction: T0MD=0x55, ACC=0xAA. after executing instruction: T0MD=0xAA.

T0MDR Move T0MD to ACC

Syntax:	T0MDR
Operand:	--
Operation:	T0MD \rightarrow ACC
Status affected:	--
Description:	Move the content of T0MD to ACC.
Cycle:	1
Example:	T0MDR before executing instruction T0MD=0x55, ACC=0xAA. after executing instruction ACC=0x55.

TFUN Load T-page SFR from ACC

Syntax:	TFUN T
Operand:	$0 \leq T \leq 14$
Operation:	ACC \rightarrow T-page SFR
Status affected:	--

TFUN Load T-page SFR from ACC

Description:	T-page SFR T is loaded by content of ACC.
Cycle:	1
Example:	TFUN T before executing instruction: T=0x55, ACC=0xAA. after executing instruction: T=0xAA, ACC=0xAA.

TFUNR Move T-page SFR to ACC

Syntax:	TFUNR T
Operand:	$0 \leq T \leq 14$
Operation:	T-page SFR \rightarrow ACC
Status affected:	--
Description:	Move T-page SFR T to ACC.
Cycle:	1
Example:	TFUNR T before executing instruction: T=0x55, ACC=0xAA. after executing instruction: T=0x55, ACC=0x55.

XORAR Exclusive-OR ACC with R

Syntax:	XORAR R, d
Operand:	$0 \leq R \leq 63$ d = 0, 1.
Operation:	ACC \oplus R \rightarrow dest
Status affected:	Z
Description:	Exclusive-OR ACC with R. If d is 0, the result is placed in ACC. If d is 1, the result is stored back to R.
Cycle:	1
Example:	XORAR R, d before executing instruction: R=0xA5, ACC=0xF0, d=1. after executing instruction: R=0x55.

XORIA Exclusive-OR Immediate with ACC

Syntax: XORIA i

Operand: $0 \leq i < 255$

Operation: $ACC \oplus i \rightarrow ACC$

Status affected: Z

Description: Exclusive-OR ACC with 8-bit
 immediate data i. The result is
 stored in ACC.

Cycle: 1

Example: XORIA i
 before executing instruction:
 i=0xA5, ACC=0xF0.
 after executing instruction:
 ACC=0x55.

5. Configuration Words

Item	Name	Options
1	High IRC Frequency	1. 1MHz 2. 2MHz 3. 4MHz 4. 8MHz 5. 16MHz 6. 20MHz
2	Instruction Clock	1. 2 oscillator period 2. 4 oscillator period
3	WDT	1. Watchdog Enable (Software control) 2. Watchdog Disable (Always disable)
4	WDT Event	1. Watchdog Reset 2. Watchdog Interrupt
5	Timer0 source	1. EX_CK1 2. I_LRC
6	PB.2	1. PB.2 is I/O 2. PB.2 is PWM 3. PB.2 is Buzzer
7	PB.3	1. PB.3 is I/O 2. PB.3 is reset
8	PB.4	1. PB.4 is I/O 2. PB.4 is instruction clock output
9	Startup Time	1. 140us 2. 4.5ms 3. 18ms 4. 72ms 5. 288ms
10	WDT Time Base	1. 3.5ms 2. 15ms 3. 60ms 4. 250ms
11	LVR Setting	1. Register Control 2. Register Control + Halt mode Off 3. Always On 4. Operation mode On + Halt mode Off
12	LVR Voltage	1. 1.6V 2. 1.8V 3. 2.0V 4. 2.2V 5. 2.4V 6. 2.7V 7. 3.0V 8. 3.4V 9. 3.6V 10. 4.2V
13	VDD Voltage	1. 3.0V 2. 4.5V 3. 5.0V
14	Read Output Data	1. I/O port 2. Register
15	EX_CK1 to Inst. Clock	1. Sync 2. Async
16	Startup Clock	1. I_HRC 2. I_LRC
17	Input High Voltage (VIH)	1. CMOS (0.7VDD) 2. TTL (0.5VDD)
18	Input Low Voltage (VIL)	1. CMOS (0.3VDD) 2. TTL (0.2VDD)
19	Input Voltage Schmitt Trigger	1. Enable (depend on 17, 18) 2. Disable (17, 18 no use)
20	Sink Current	1. Normal 2. Large
21	Comparator Input pin select	1. Enable 2. Disable

Table 15 Configuration Words

6. Electrical Characteristics

6.1 Absolute Maximum Rating

Symbol	Parameter	Rated Value	Unit
$V_{DD} - V_{SS}$	Supply voltage	-0.5 ~ +6.0	V
V_{IN}	Input voltage	$V_{SS}-0.3V \sim V_{DD}+0.3$	V
T_{OP}	Operating Temperature	-40 ~ +85	°C
T_{ST}	Storage Temperature	-40 ~ +125	°C

6.2 DC Characteristics

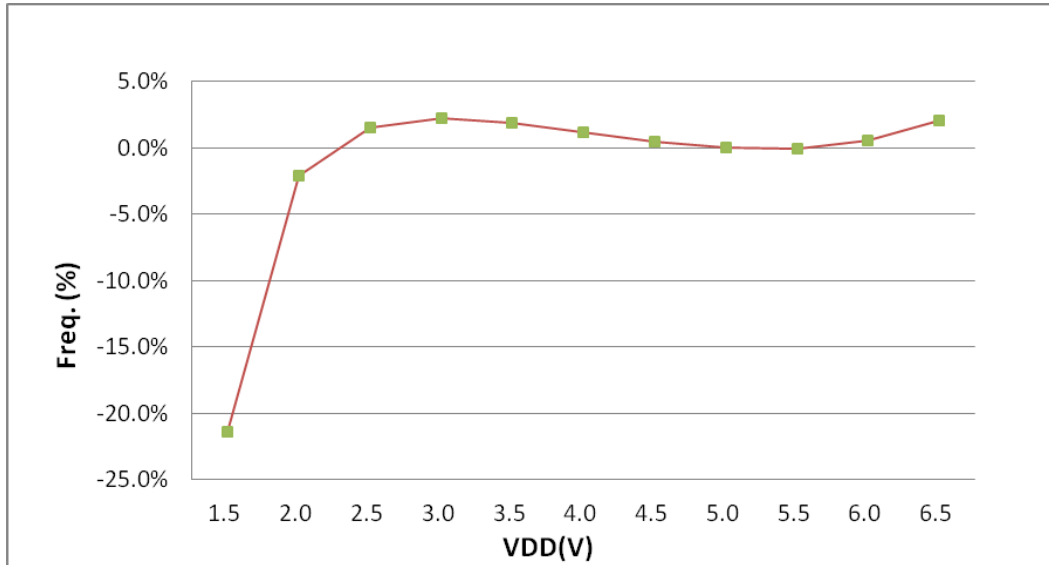
(All refer $F_{INST}=F_{HOSC}/4$, $F_{HOSC}=16MHz@I_HRC$, WDT enabled, ambient temperature $T_A=25^{\circ}C$ unless otherwise specified.)

Symbol	Parameter	V_{DD}	Min.	Typ.	Max.	Unit	Condition
V_{DD}	Operating voltage	--	3.3	--	5.5	V	$F_{INST}=20MHz @ I_HRC/2$
			2.2				$F_{INST}=20MHz @ I_HRC/4$
			3.0				$F_{INST}=16MHz @ I_HRC/2$
			2.0				$F_{INST}=16MHz @ I_HRC/4$
			2.0				$F_{INST}=8MHz @ I_HRC/4$
			1.6				$F_{INST}=4MHz @ I_HRC/4$
			1.6				$F_{INST}=2MHz @ I_HRC/4$
			1.6				$F_{INST}=1MHz @ I_HRC/4$
			1.6				$F_{INST}=32KHz @ I_LRC/4 \& I_LRC/2$
V_{IH}	Input high voltage	5V	4.0	--	--	V	RSTb (0.8 V_{DD})
		3V	2.4	--	--		
		5V	3.5	--	--	V	All other I/O pins, EX_CKI, INT CMOS (0.7 V_{DD})
		3V	2.1	--	--		
		5V	2.5	--	--	V	All other I/O pins, EX_CKI, INT TTL (0.5 V_{DD})
		3V	1.5	--	--		
		5V	2.1	--	--	V	All other I/O pins, EX_CKI, INT No Schmitt Trigger (0.5 V_{DD})
		3V	1.3	--	--		
V_{IL}	Input low voltage	5V	--	--	1.0	V	RSTb (0.2 V_{DD})
		3V	--	--	0.6		
		5V	--	--	1.5	V	All other I/O pins, EX_CKI, INT CMOS (0.3 V_{DD})
		3V	--	--	0.9		
		5V	--	--	1.0	V	All other I/O pins, EX_CKI, INT TTL (0.2 V_{DD})
		3V	--	--	0.6		
		5V	--	--	2.1	V	All other I/O pins, EX_CKI, INT No Schmitt Trigger (0.5 V_{DD})
		3V	--	--	1.3		
I_{OH}	Normal Drive Current	5V	--	-16	--	mA	$V_{OH}=4.0V$
		3V	--	-10	--		$V_{OH}=2.0V$
		5V	--	25	--		$V_{OL}=1.0V$
I_{OL}	Normal Sink	5V	--	25	--	mA	$V_{OL}=1.0V$

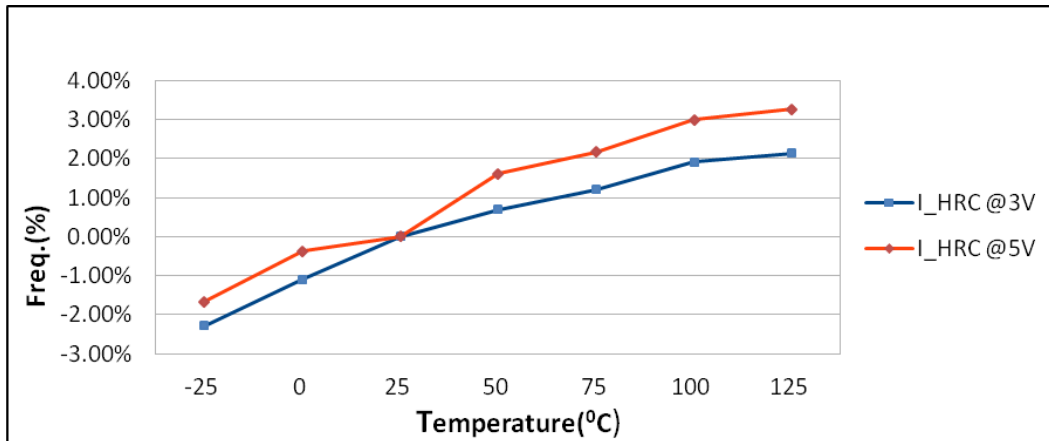
Symbol	Parameter	V _{DD}	Min.	Typ.	Max.	Unit	Condition
	Current	3V	--	15	--	mA	V _{OL} =1.0V
	Large Sink Current	5V	--	40	--		
		3V	--	22	--		
I _{IR}	IR sink current	5V	--	40	--	mA	V _{OL} =1.0V, Large Sink On.
		3V	--	22	--		
I _{OP}	Operating current	Normal Mode					
		5V	--	3.7	--	mA	F _{HOSC} =20MHz @ I _{HRC} /2
		3V	--	2.6	--		
		5V	--	2.9	--	mA	F _{HOSC} =20MHz @ I _{HRC} /4
		3V	--	2.2	--		
		5V	--	3.4	--	mA	F _{HOSC} =16MHz @ I _{HRC} /2
		3V	--	2.5	--		
		5V	--	2.8	--	mA	F _{HOSC} =16MHz @ I _{HRC} /4
		3V	--	2.1	--		
		5V	--	2.8	--	mA	F _{HOSC} =8MHz @ I _{HRC} /2
		3V	--	2.1	--		
		5V	--	2.3	--	mA	F _{HOSC} =8MHz @ I _{HRC} /4
		3V	--	1.9	--		
		5V	--	2.3	--	mA	F _{HOSC} =4MHz @ I _{HRC} /2
		3V	--	1.9	--		
		5V	--	0.8	--	mA	F _{HOSC} =4MHz @ I _{HRC} /4
		3V	--	0.7	--		
		5V	--	0.5	--	mA	F _{HOSC} =1MHz @ I _{HRC} /2
		3V	--	0.4	--		
		5V	--	0.3	--	mA	F _{HOSC} =1MHz @ I _{HRC} /4
		3V	--	0.3	--		
		Slow mode					
		5V	--	16	--	uA	F _{HOSC} disabled, F _{LOSC} =32KHz @ I _{LRC} /2
		3V	--	13	--		
		5V	--	10	--	uA	F _{HOSC} disabled, F _{LOSC} =32KHz @ I _{LRC} /4
		3V	--	7	--		
I _{STB}	Standby current	5V	--	3.0	--	uA	Standby mode, F _{HOSC} disabled, F _{LOSC} =32KHz @ I _{LRC} /4
		3V	--	1.3	--		
I _{HALT}	Halt current	5V	--	--	0.5	uA	Halt mode, WDT disabled.
		3V	--	--	0.2		
		5V	--	--	5	uA	Halt mode, WDT enabled.
		3V	--	--	2		
R _{PH}	Pull-High resistor	5V	--	53	--	kΩ	Pull-High resistor
		3V	--	106	--		
R _{PL}	Pull-Low resistor	5V	--	57	--	kΩ	Pull-Low resistor
		3V	--	114	--		

6.3 Characteristic Graph

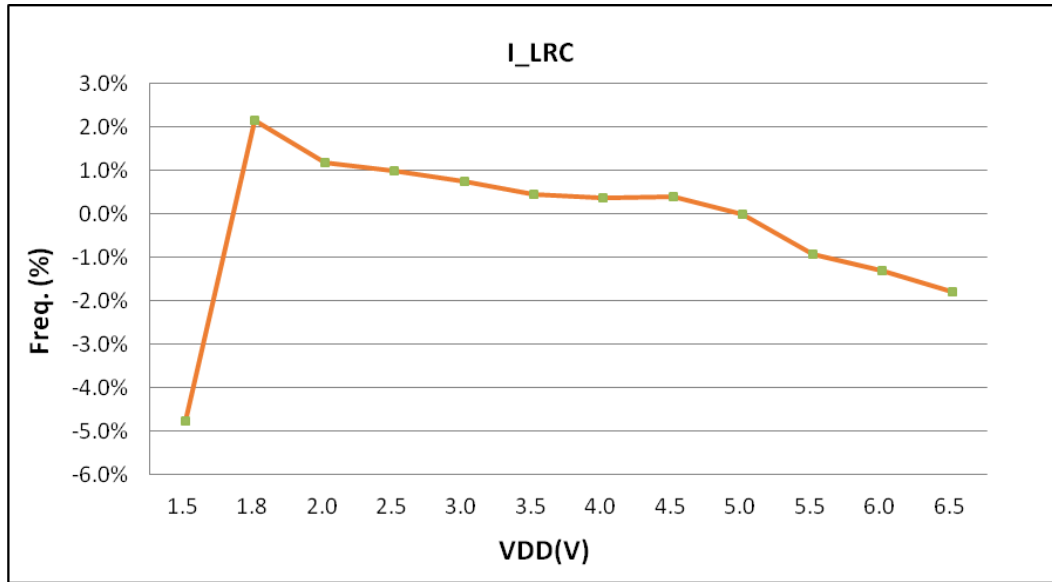
6.3.1 Frequency vs. V_{DD} of I_HRC



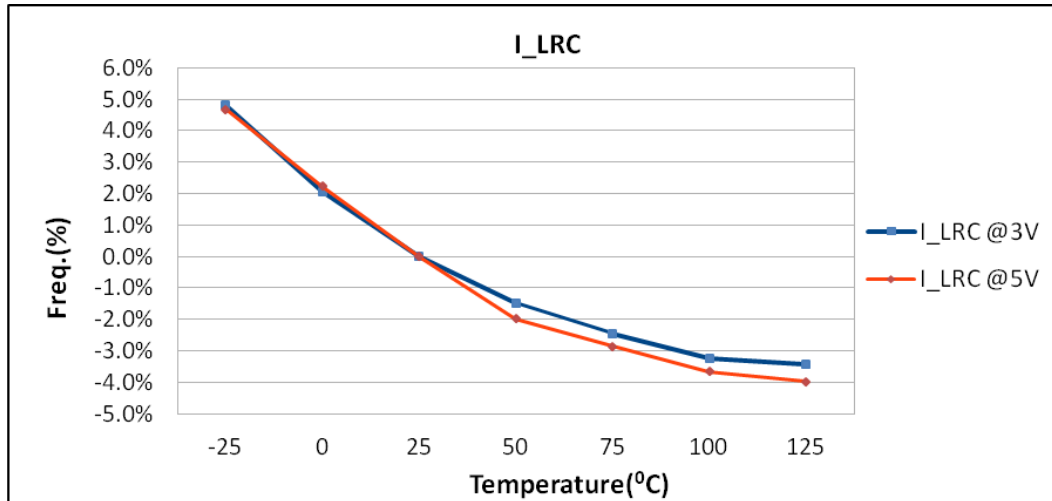
6.3.2 Frequency vs. Temperature of I_HRC



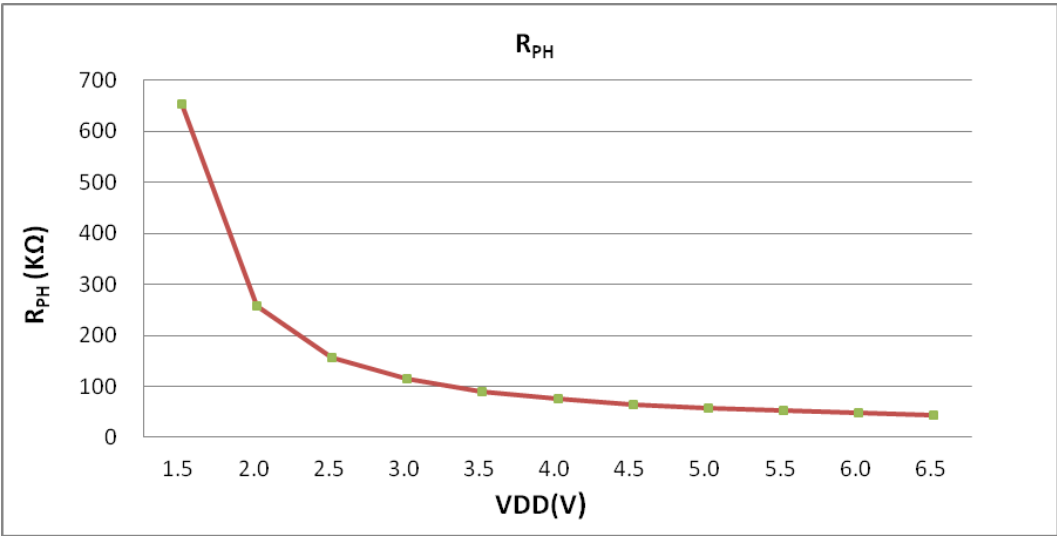
6.3.3 Frequency vs. V_{DD} of I_LRC



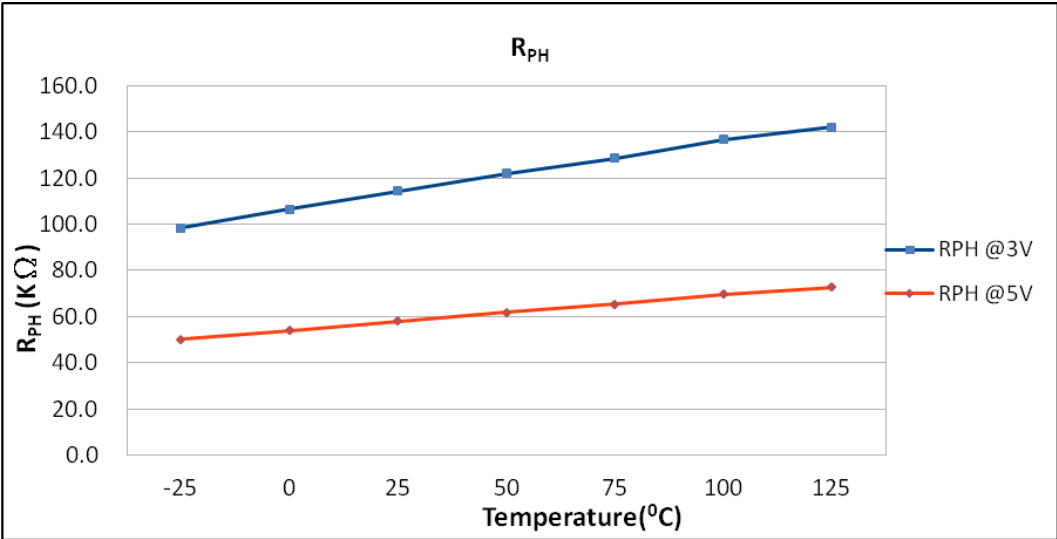
6.3.4 Frequency vs. Temperature of I_LRC



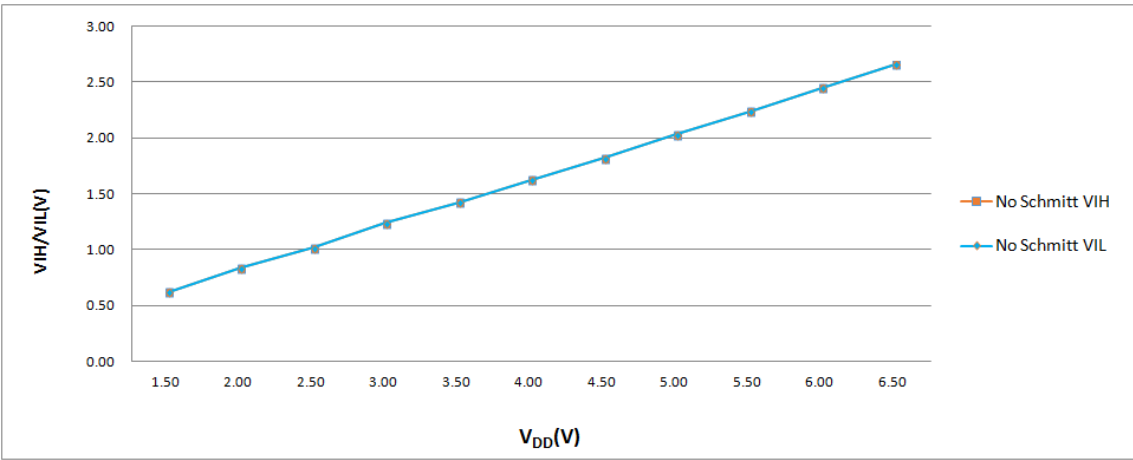
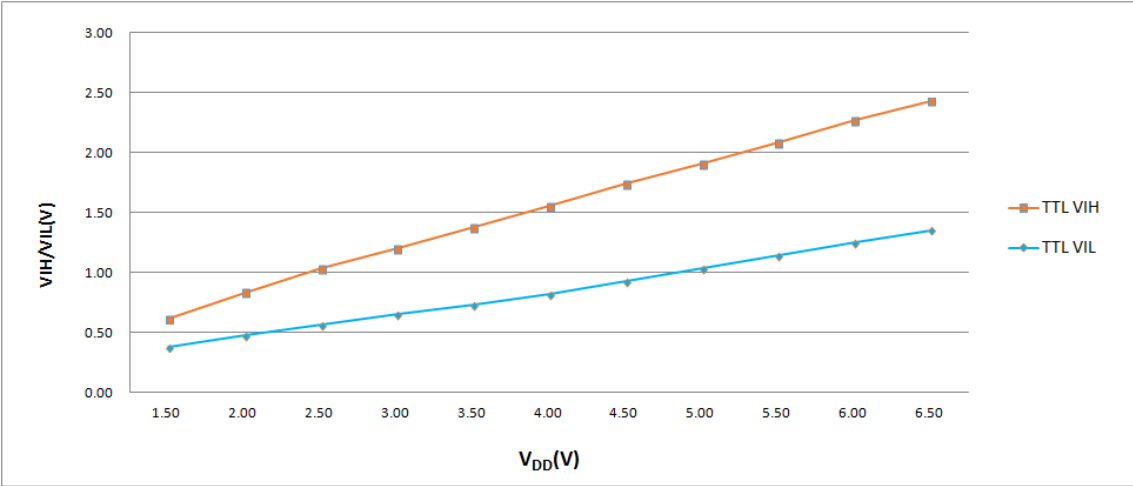
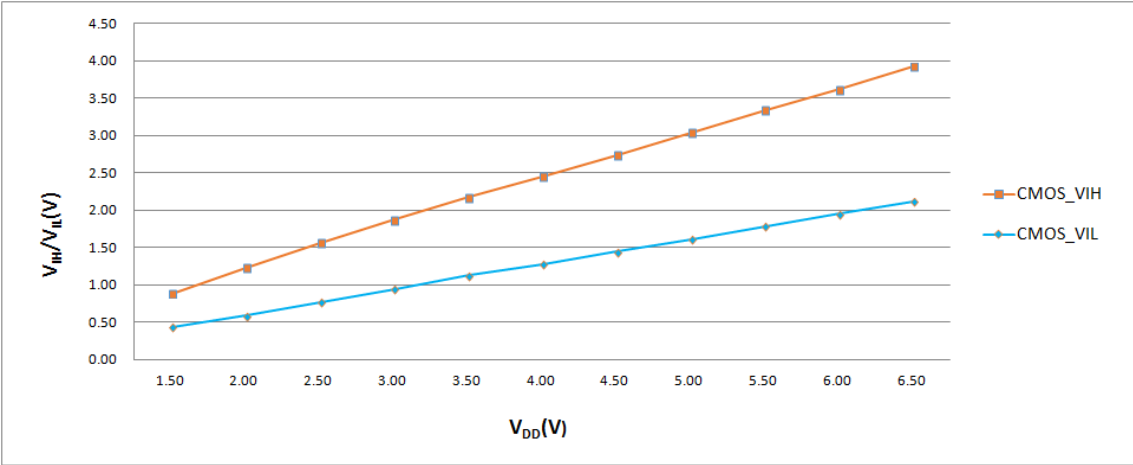
6.3.5 Pull High Resistor vs. VDD

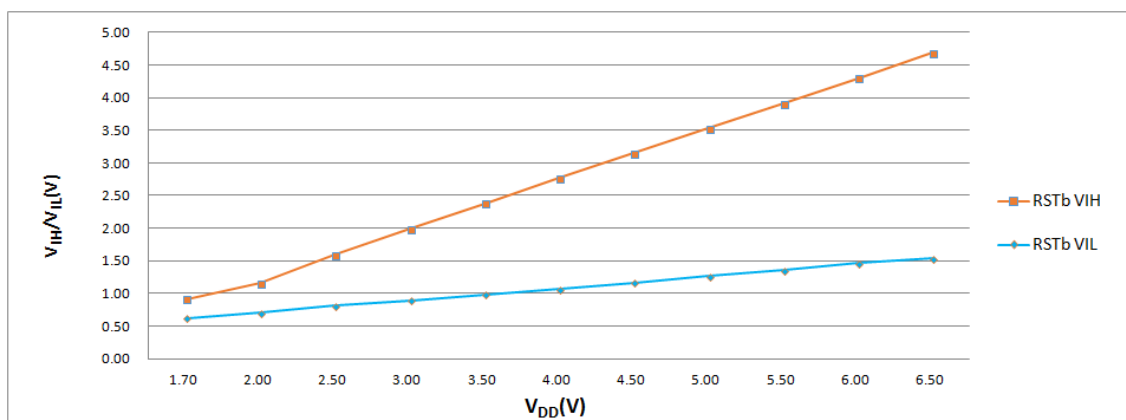


6.3.6 Pull High Resistor vs. Temperature

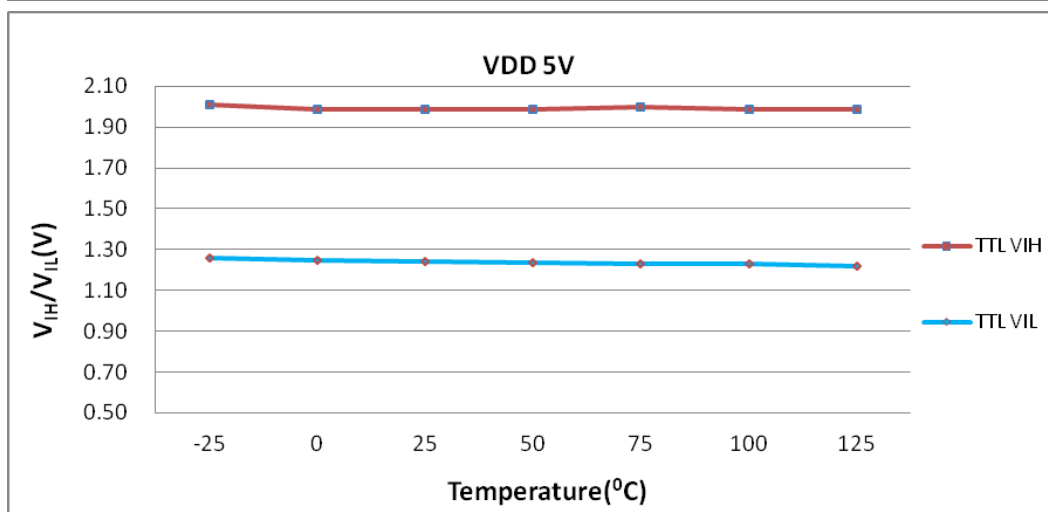
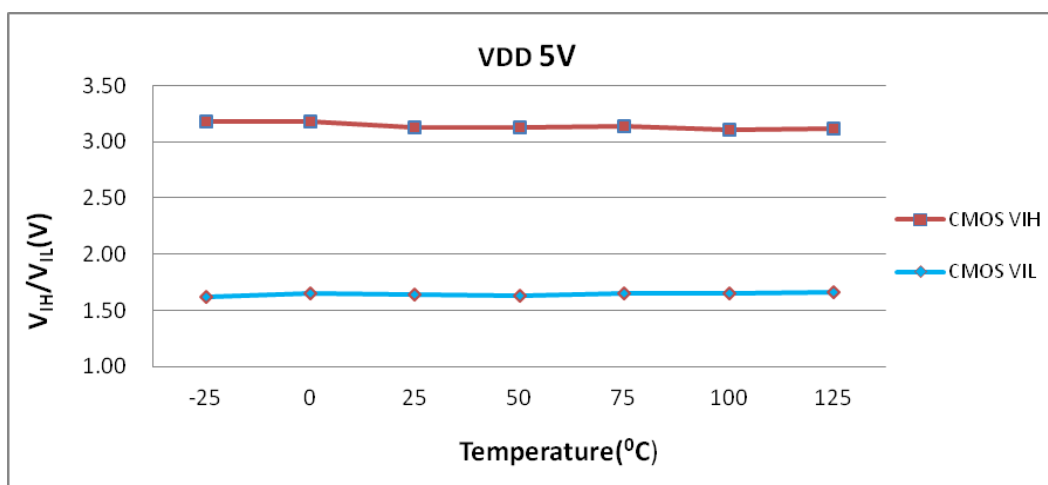


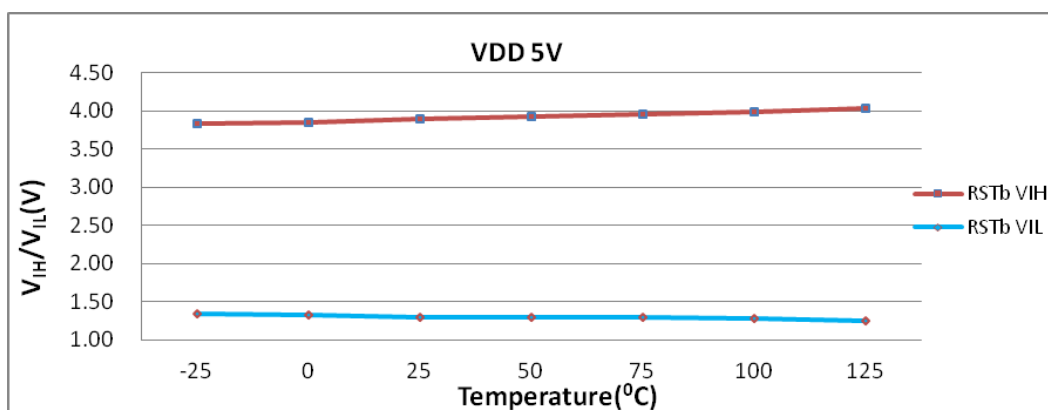
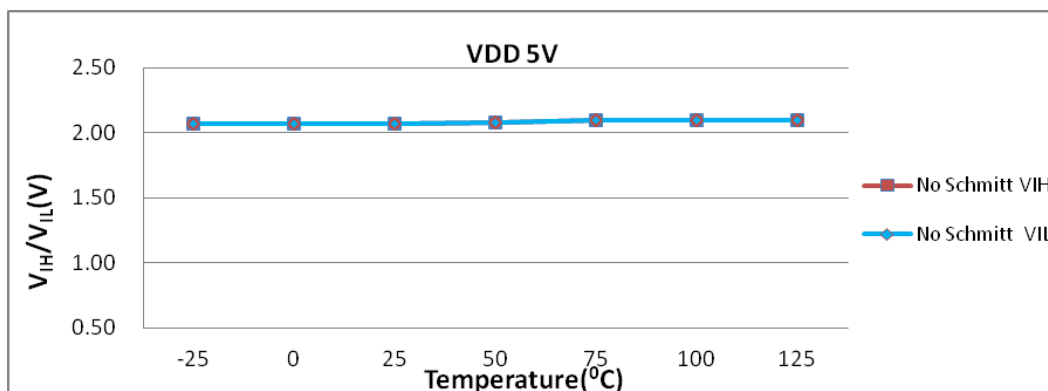
6.3.7 VIH/VIL vs. VDD





6.3.8 VIH/VIL vs. Temperature



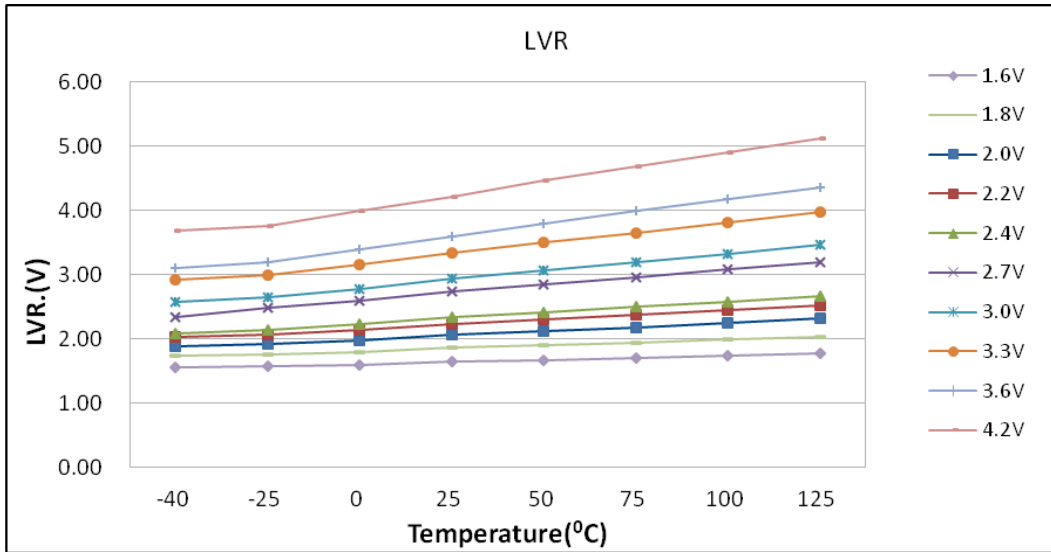


6.4 Recommended Operating Voltage

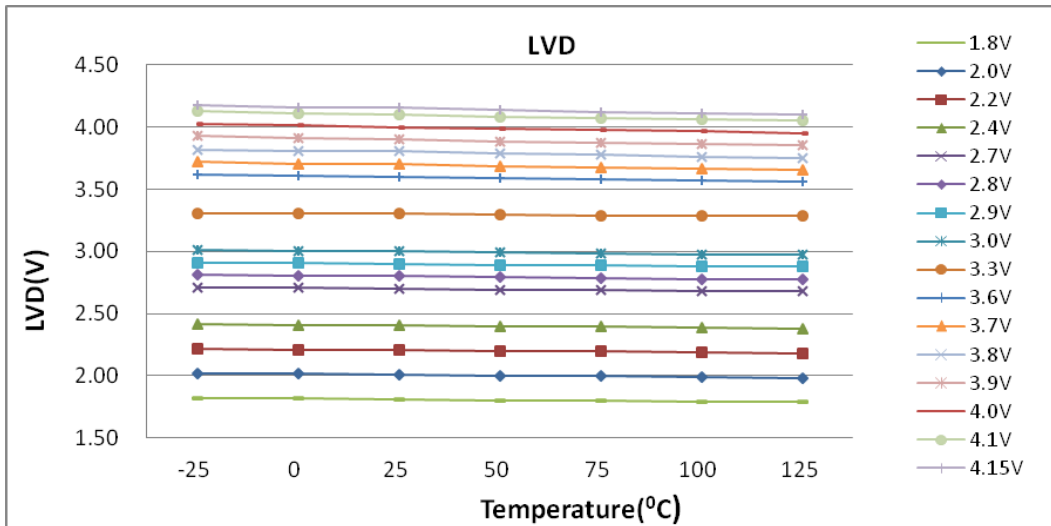
Recommended Operating Voltage (Temperature range: -40 °C ~ +85 °C)

Frequency	Min. Voltage	Max. Voltage	LVR : default (25 °C)	LVR : Recommended (-40 °C ~ +85 °C)
20M/2T	3.0V	5.5V	3.0V	3.4V
16M/2T	2.6V	5.5V	3.0V	3.0V
20M/4T	2.1V	5.5V	2.4V	2.4V
16M/4T or 8M/2T	1.9V	5.5V	2.2V	2.4V
8M/4T or 4M/2T	1.5V	5.5V	2.0V	2.2V
4M/4T or 2M/2T	1.5V	5.5V	2.0V	2.2V
2M/4T or 1M/2T	1.5V	5.5V	2.0V	2.2V
1M/4T	1.5V	5.5V	2.0V	2.2V

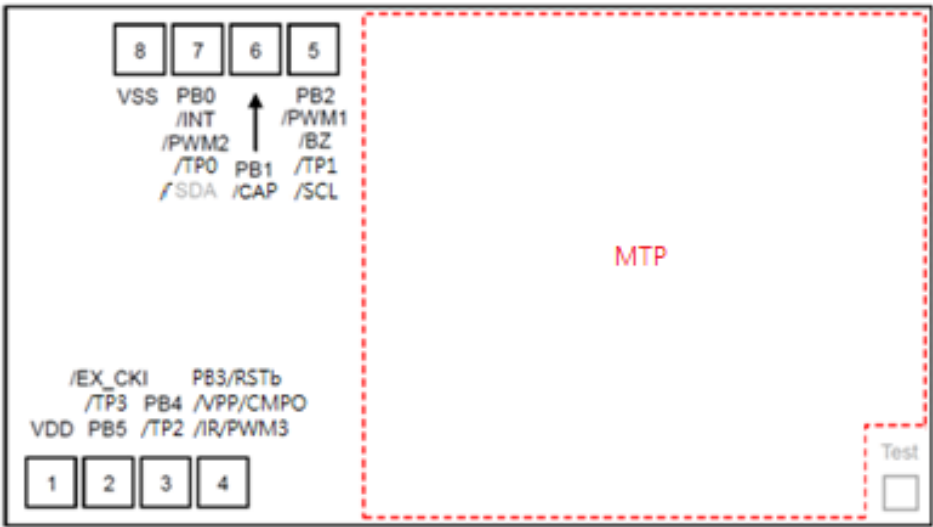
6.5 LVR vs. Temperature



6.6 LVD vs. Temperature

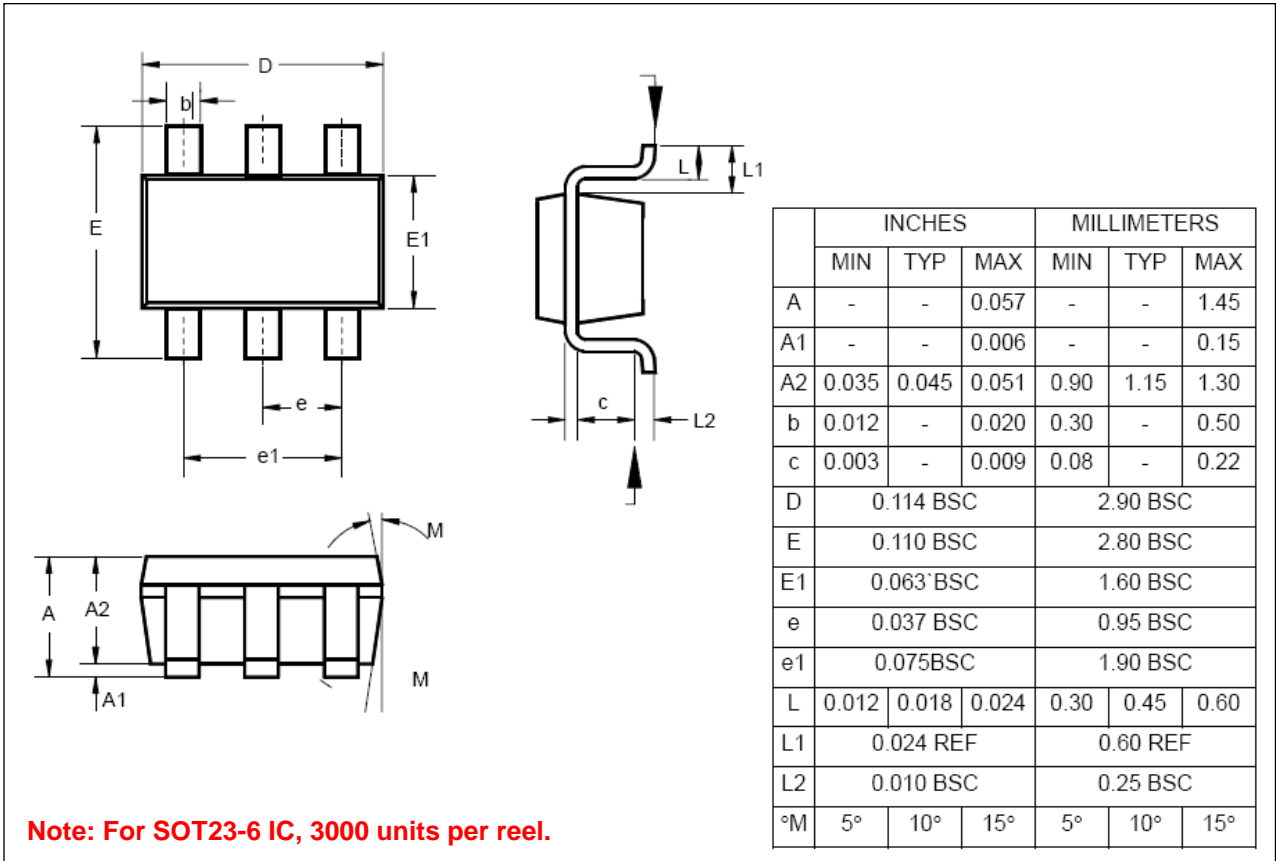


7. Die Pad Diagram

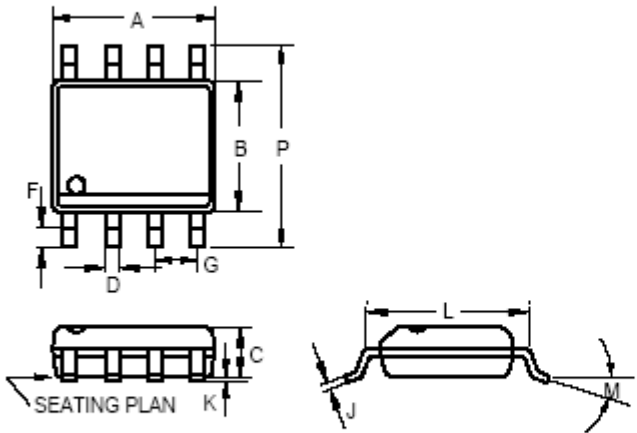


8. Package Dimension

8.1 6-Pin Plastic SOT23-6 (63 mil)



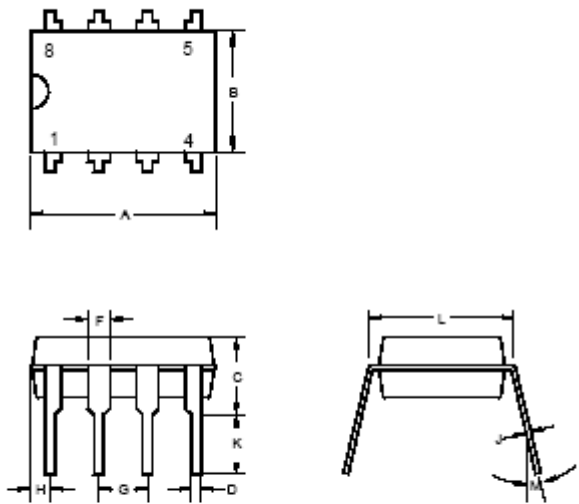
8.2 8-Pin Plastic SOP (150 mil)



Note: For 8-pin SOP, 100 units per tube.

	INCHES			MILLIMETERS		
	MIN	TYP	MAX	MIN	TYP	MAX
A	0.183	-	0.202	4.65	-	5.13
B	0.144	-	0.163	3.66	-	4.14
C	0.068	-	0.074	1.35	-	1.88
D	0.010	-	0.020	0.25	-	0.51
F	0.015	-	0.035	0.38	-	0.89
G	0.050 BSC			1.27 BSC		
J	0.007	-	0.010	0.19	-	0.25
K	0.005	-	0.010	0.13	-	0.25
L	0.189	-	0.205	4.80	-	5.21
M	-	-	8°	-	-	8°
P	0.228	-	0.244	5.79	-	6.20

8.3 8-Pin Plastic DIP (300 mil)



Note: For 8-pin Plastic DIP, 50 units per tube.

	INCHES			MILLIMETERS		
	MIN	TYP	MAX	MIN	TYP	MAX
A	0.355	0.365	0.400	9.02	9.27	10.16
B	0.240	0.250	0.280	6.10	6.35	7.11
C	-	-	0.210	-	-	5.33
D	-	0.018	-	-	0.46	-
F	-	0.060	-	-	1.52	-
G	-	0.100	-	-	2.54	-
H	0.050	-	0.090	1.27	-	2.29
J	0.008	-	0.015	0.20	-	0.38
K	0.115	0.130	0.150	2.92	3.30	3.81
L	0.300 BSC.			7.62 BSC.		
M	-	7°	15°	-	7°	15°

9. Ordering Information

<i>P/N</i>	<i>Package Type</i>	<i>Pin Count</i>	<i>Package Width</i>	<i>Shipping</i>
NY8TM52D	Die	--	--	--
NY8TM52DS6	SOT23-6	6	63 mil	<u>Tape & Reel</u> : 3.0K pcs per Reel
NY8TM52DS8	SOP	8	150 mil	<u>Tape & Reel</u> : 2.5K pcs per Reel <u>Tube</u> : 100 pcs per Tube
NY8TM52DP8	PDIP	8	300 mil	<u>Tube</u> : 50 pcs per Tube